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# **Progress and Planned Future Directions in Optical Processing and Communications**

## **DARPA/MTO Microsystems Technology Symposium**

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**Santa Barbara, CA 93106**

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LASOR research supported under DARPA/MTO DoD-N Program Award Number W911NF-04-9-0001  
CSWDM research supported under DARPA/MTO Program Award Number

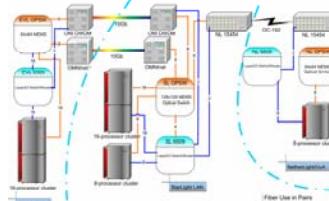
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# Technology Push and Integration Trends

- (a) Transistor
- (b) Million to Billion transistor integration
- (c) Heterojunction Laser, Optical Waveguides, Integrated & Silicon Photonics
- (d) Heterojunction Integrated Optoelectronics
- (e) Vertical Memory Storage

NEC earth simulator



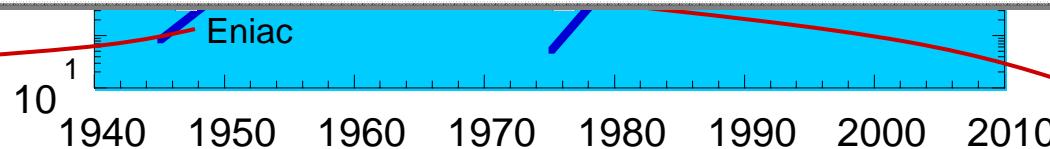
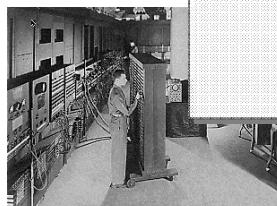
Cisco CRS-1 (92 Tbps  
- 40 Racks)



Systems  
on-chip  
; for chip-to-  
processor  
or chips



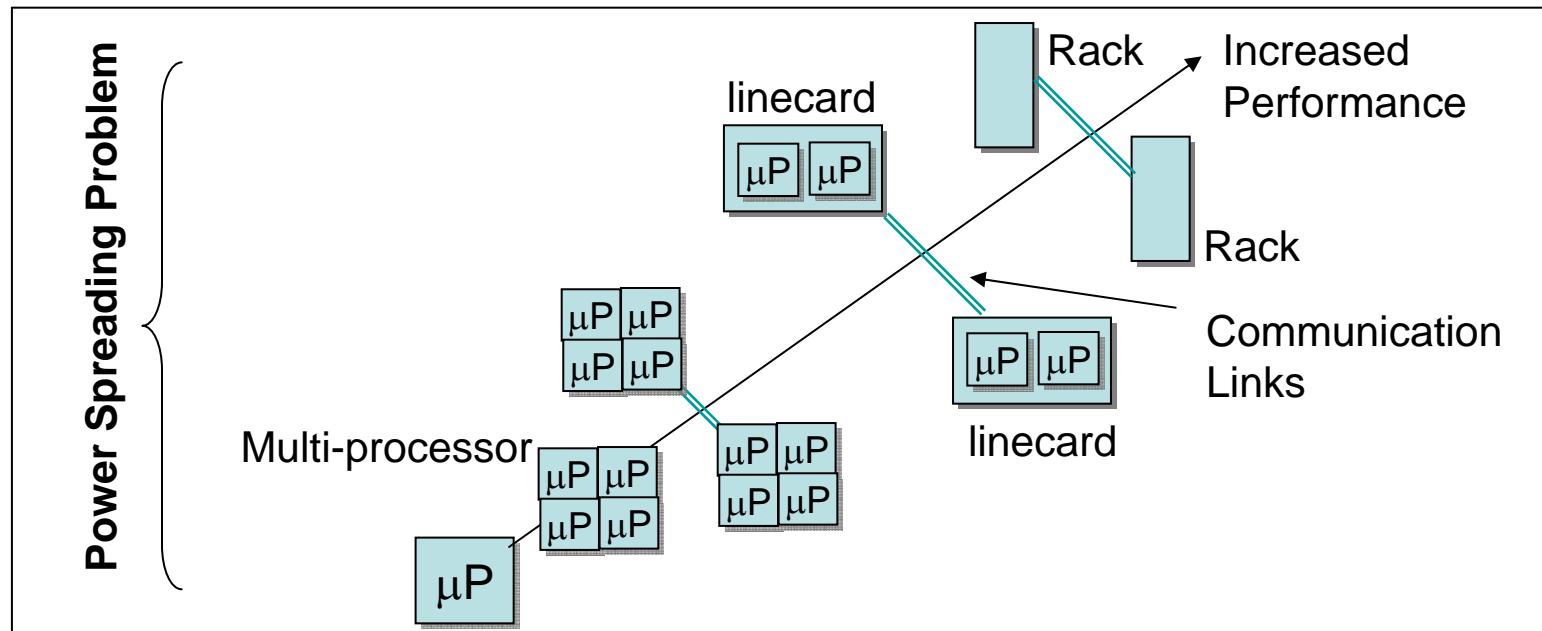
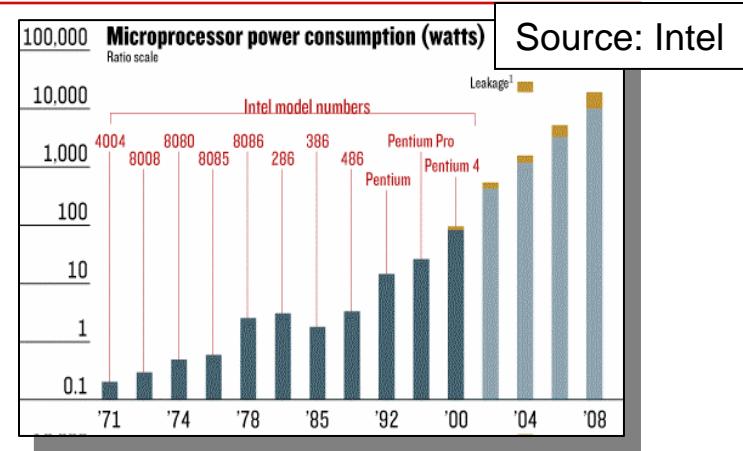
Approximately every 10 years we see the results of basic technology research reduce systems from lab size to the desktop size. This trend enables vast new applications that cannot be fully forecast.





# Power and Size: The Next Frontier

- Decreased transistor size, 2x transistors on chip every 18 months, increased frequency
- Leakage current is huge problem, chips (hence systems) become power constrained
- New transistor technologies aim to decrease leakage current but requires new processing infrastructure. Costly to roll over to new foundries from current.
- Moving to multi-processor cores to keep up performance without increasing speed





# Technical Contributors

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## CSWDM

**Integrated Optical Wavelength Converters and Routers for Robust Wavelength-Agile Analog/ Digital Optical Networks**

**UCSB:** M. Masanovic, V. Lal, J. Summers, H. -F Chou, E. Skogen, J. S. Barton M. Sysak, D. J. Blumenthal, J. E. Bowers, L. A. Coldren, N. Dagli, E. Hu

## DoD-N

**LASOR: A Label Switched Optical Router**

**Cisco Systems:** D. Civello, G. Epps

**JDSUniphase:** C. Coldren, G. Fish

**Stanford University:** N. Beheshti, Y. Ganjali, N. McKeown

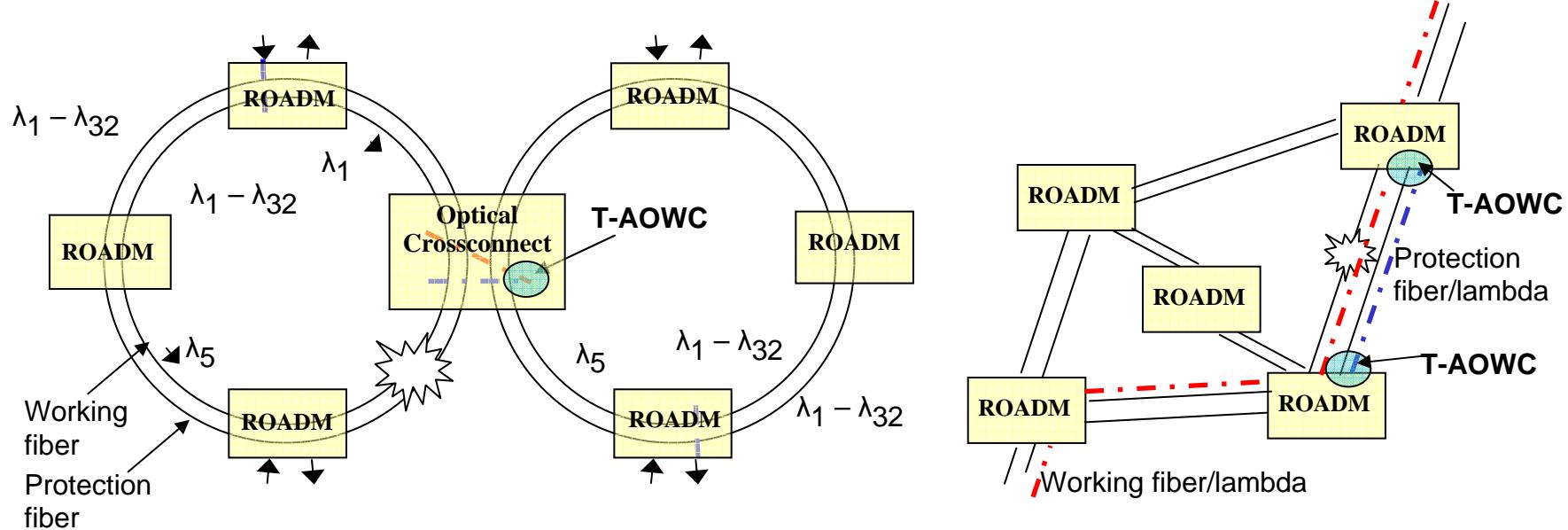
**UCSB:** B. Koch, M. Chun, L. Garza, M. Mashanovitch, J. Barton, T. Berg, J. Mack, H. Poulsen, S. Nicholes, E. Burmeister, H. Park, M. Dummer, A. Tauke-Pedretti, B. Stamenic, D. J. Blumenthal, J. E. Bowers, L. A. Coldren



# CSWDM- Motivation and Applications



- ✿ Monolithically integrate widely tunable digital and analog wavelength conversion from any input  $\lambda$  to any output  $\lambda$
- ✿ Make tunable wavelength converters inexpensive to use
- ✿ Eliminate off-chip high speed electrical for WC and regeneration
- ✿ Analog operation to 20GHz
- ✿ Integrate signal quality monitoring
- ✿ Push limits of on-chip component and function density

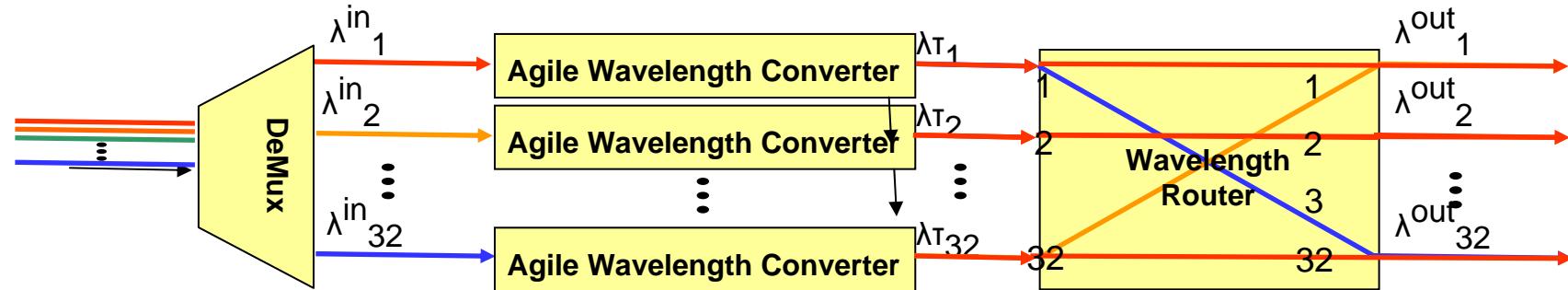




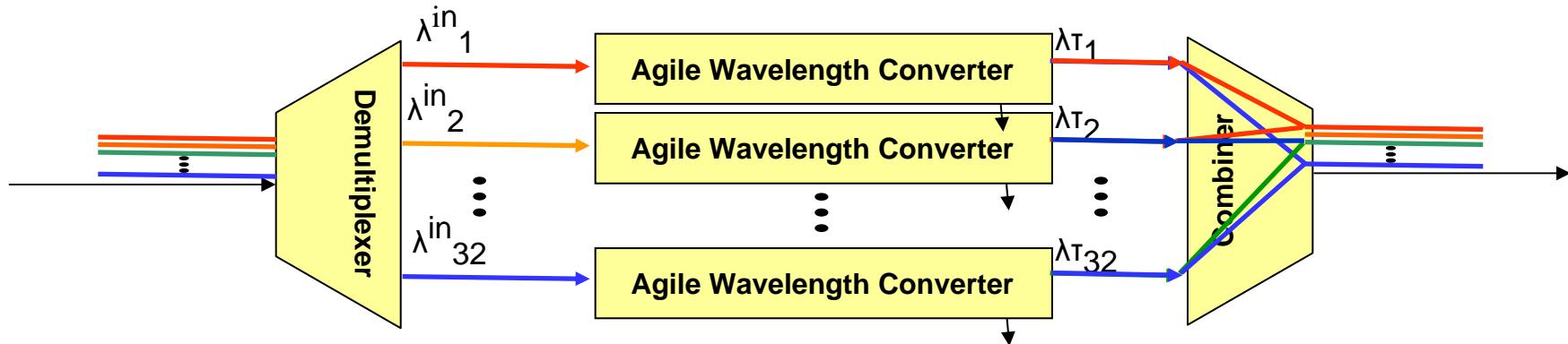
# CS-WDM

## All-Optical Switching on-Chip for DoD Applications

### Wavelength/Space Switch



### Wavelength Interchanger

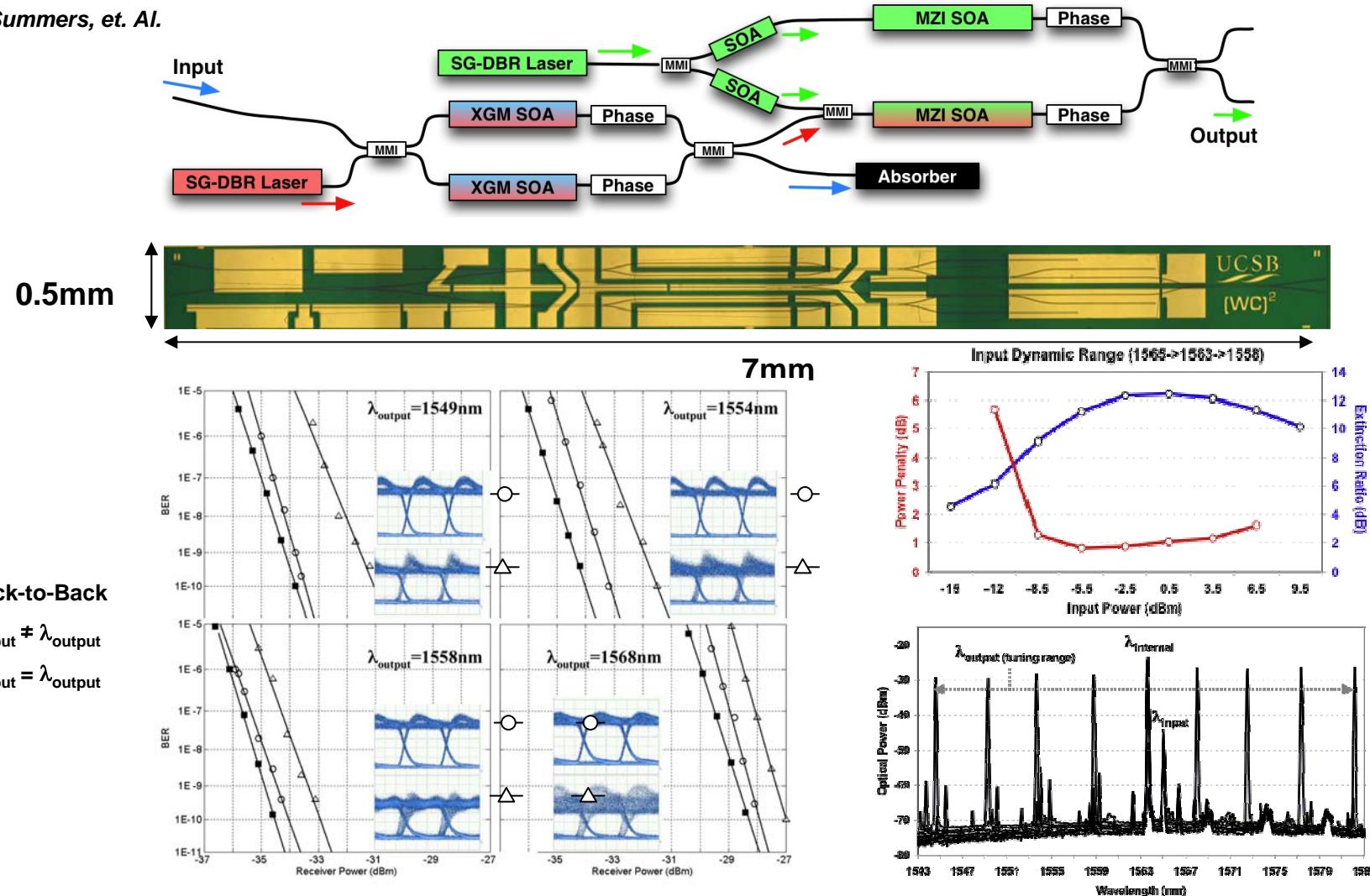




# CS-WDM

## 2-Stage Tunable Wavelength Converters

J. Summers, et. Al.

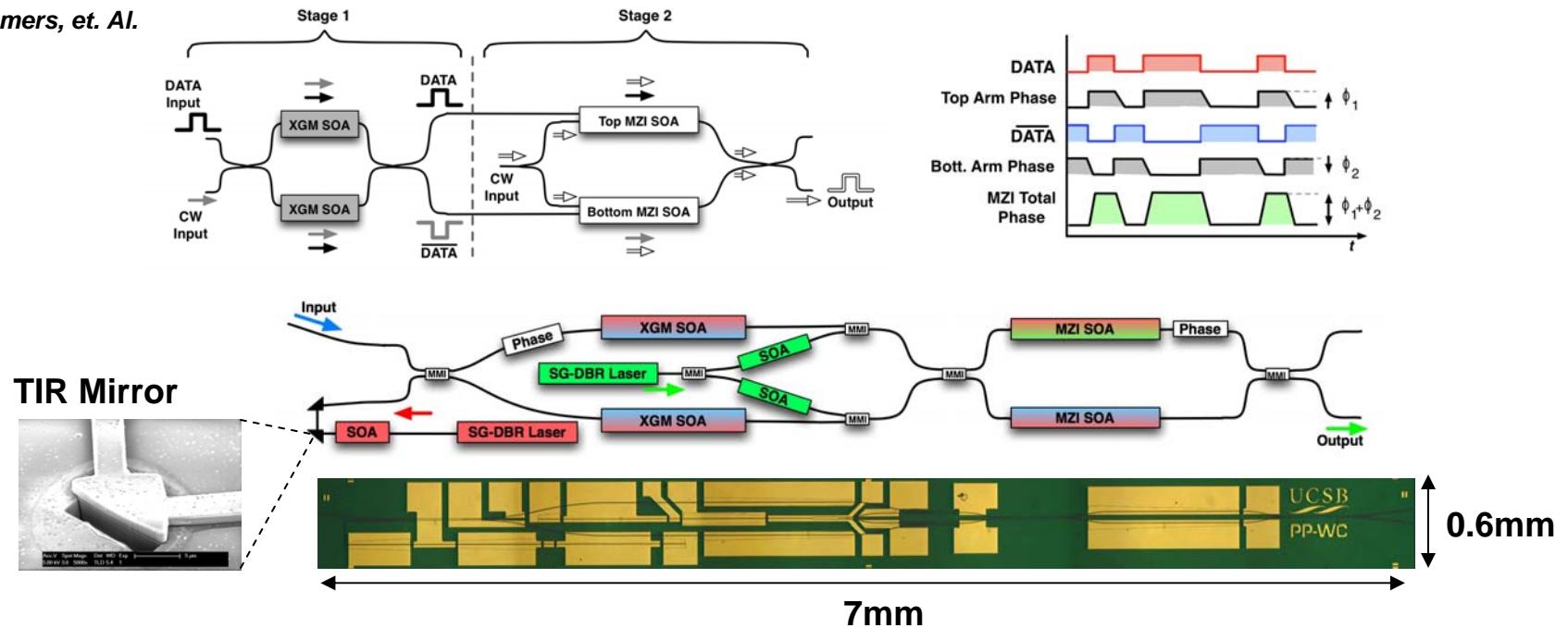




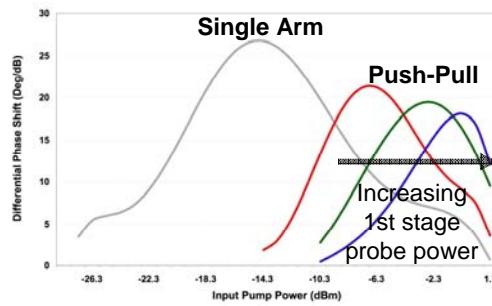
# CS-WDM

## All-Optical Push-Pull Wavelength Converters

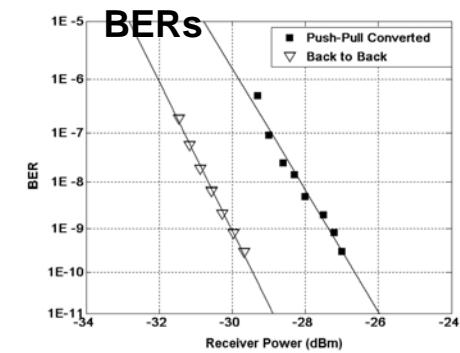
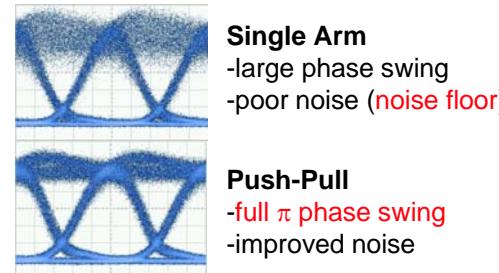
J. Summers, et. Al.



### Phase Measurements



### Eye Diagrams

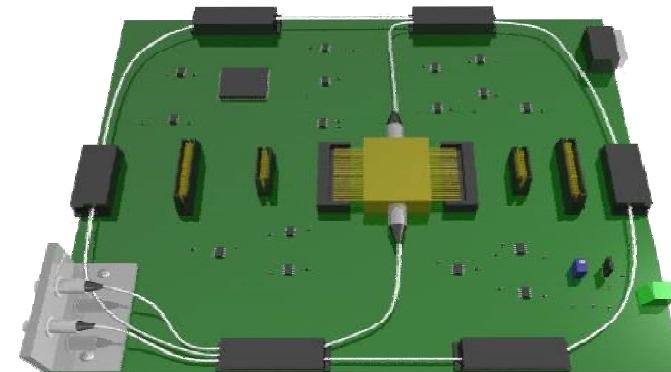
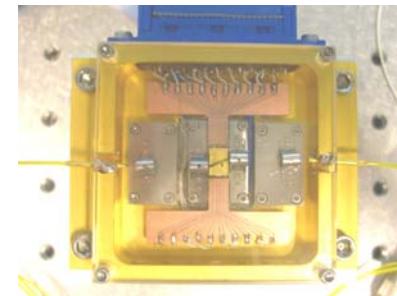
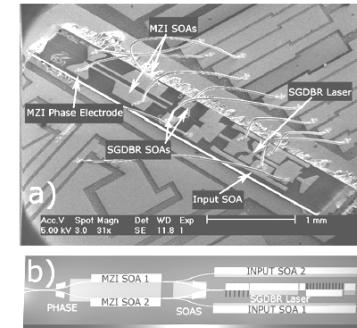




# CS-WDM

## Materials-Device-Function-System

- 1<sup>st</sup> generation: Feb. '04
  - Chip-on-carrier 2.5Gbs wavelength tunable all-optical wavelength converters sent to MIT-LL.
- 2<sup>nd</sup> generation: Aug. '05
  - Packaged 2.5Gbps T-AOWCs sent to MIT-LL.
- 3<sup>rd</sup> generation: Dec. '05 - Jan. '06
  - (4) x T-AOWCs packaged and integrated on control circuit boards installed on in-flight demo.



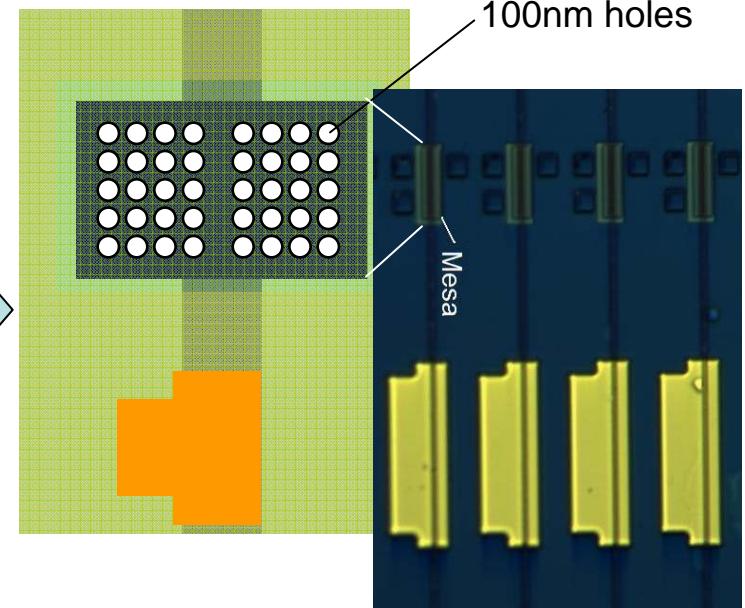
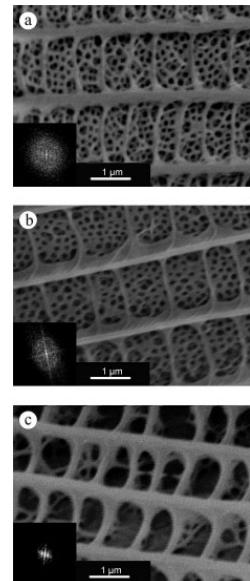


# CS-WDM

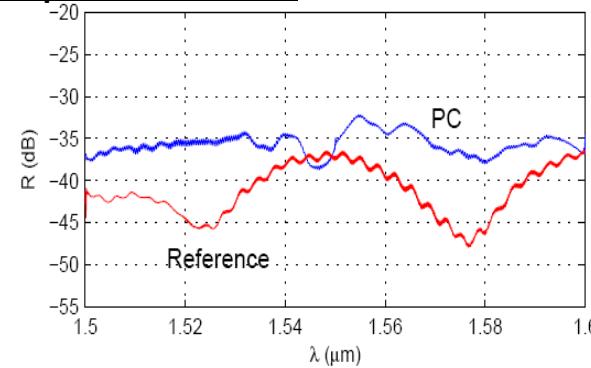
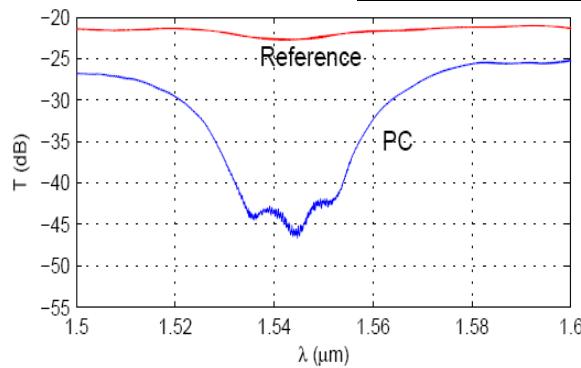
## Manipulating Light with Photonic Crystals



Butterfly Wings - Color + Cooling



### Ultra-Short Optical Filters



$L=30\mu\text{m}$

*M. Davanço, A. Xing, J. Raring,  
E. L. Hu, and D.J. Blumenthal\**  
“Broadband Photonic Crystal  
Passive Filters for Monolithically  
Integrated InP Photonic  
Integrated Circuits,” Submitted to  
OFC 2006.

## Where Does Integrated Photonics Fit into the Picture?

Process and  
switch photons  
around to  
reduce power

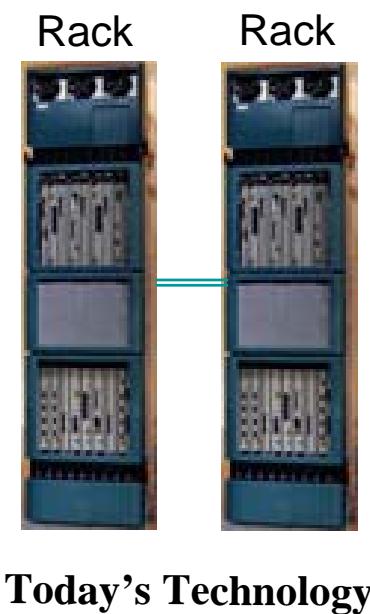
Integrate  
Photonic  
Functions onto  
a Chip to  
reduce size

Photonic  
Integrated  
Circuits (PICs)  
still at 1960s of  
Electronics

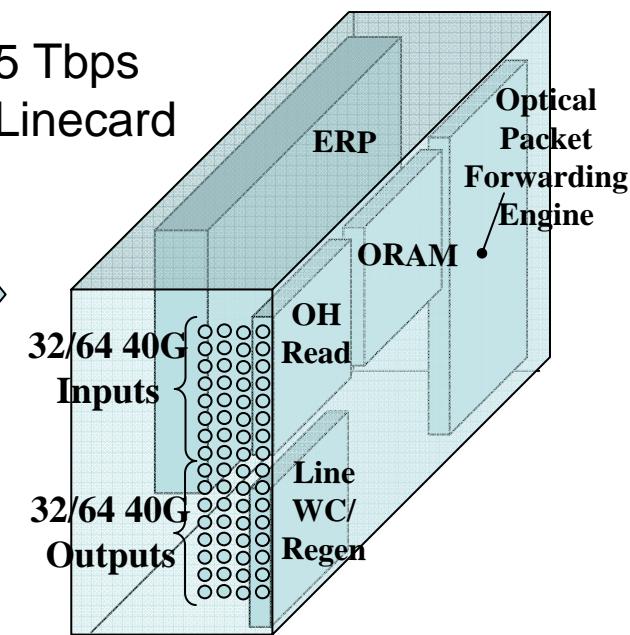
Research in:

- Physics
- Materials
- Devices and PICs
- Processing
- Architectures

- DARPA MTO DOD-N Program - LASOR (Haney, Shah)
- UCSB: Blumenthal, Bowers, Coldren
- Stanford: McKeown
- Cisco
- JDSU

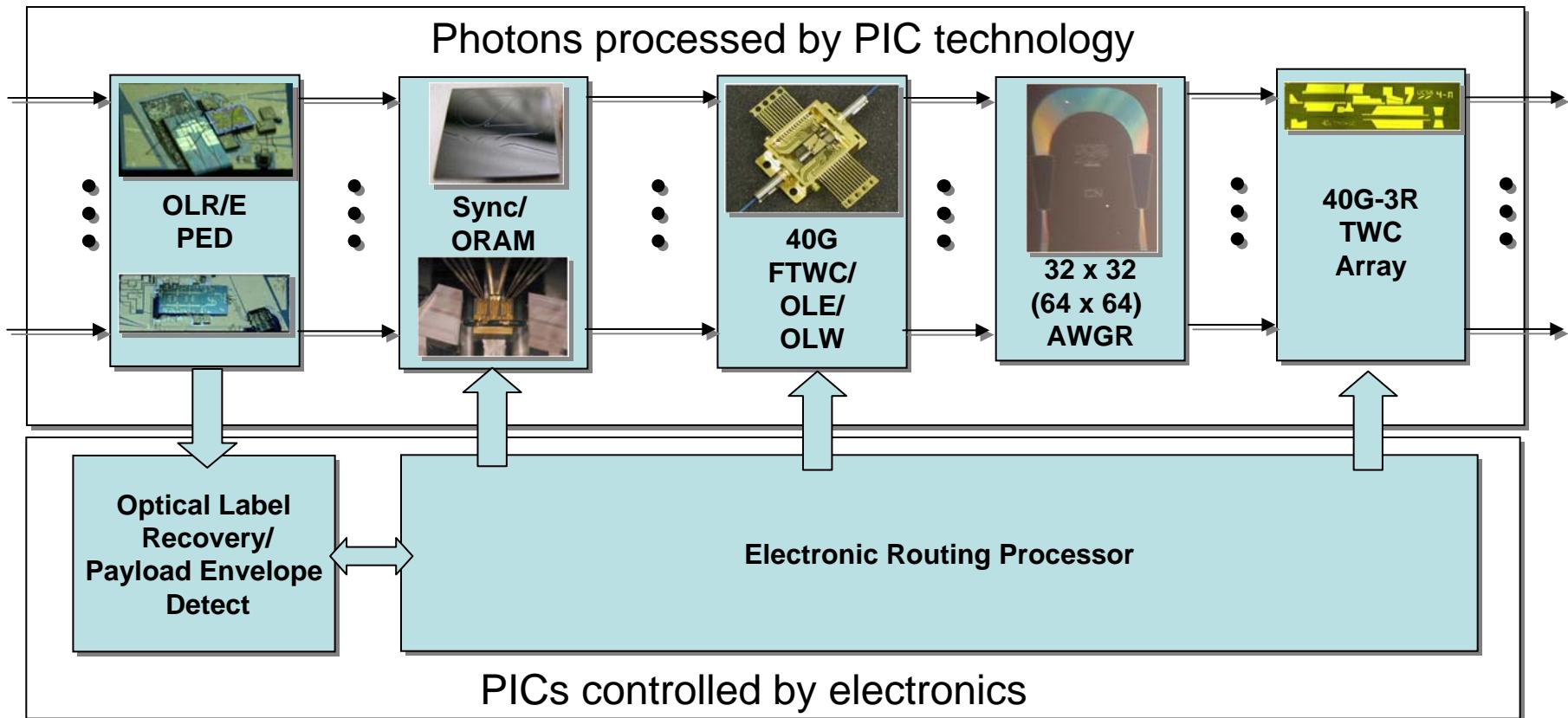


5 Tbps  
Linecard



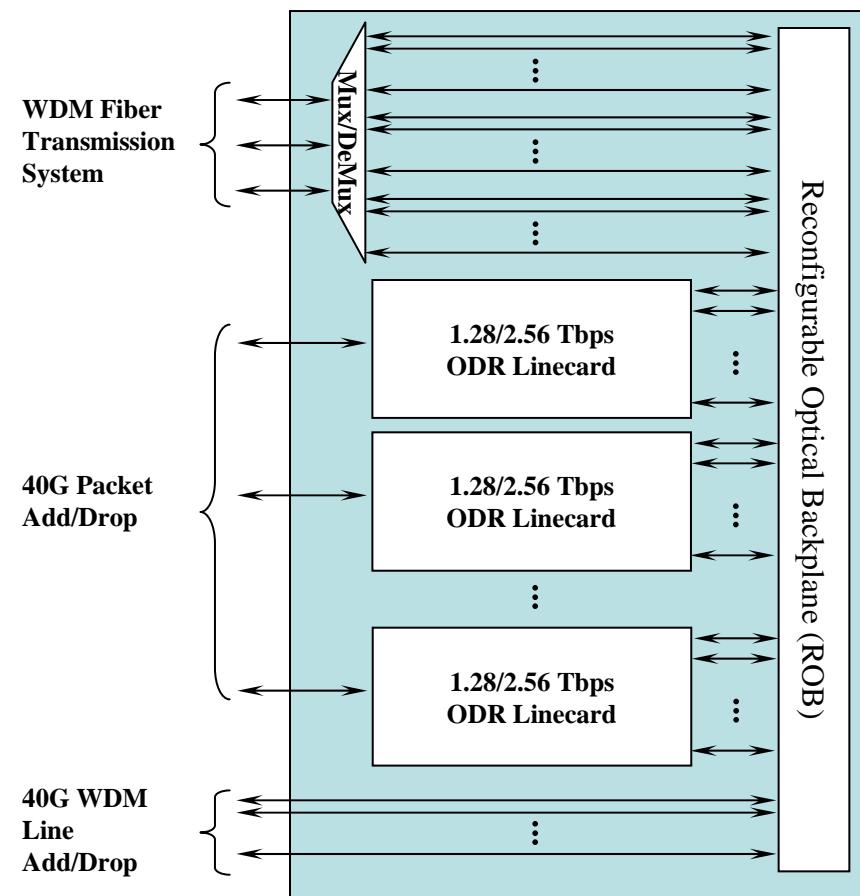
## LASOR Optical Packet Router Linecard

Pushing envelope on density and functionality of InP and Silicon Photonics

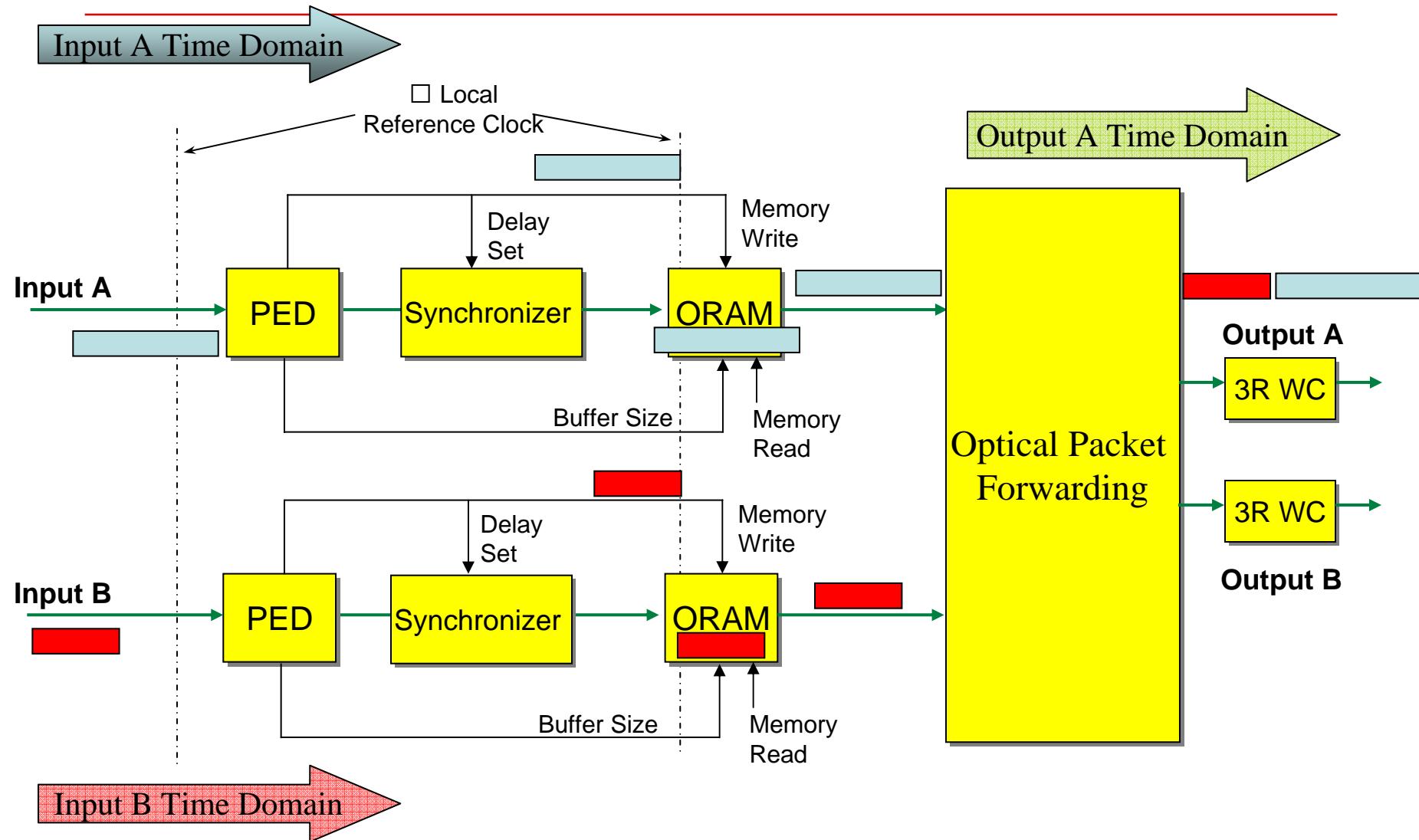


# 100 Tbps Optical Routing Node

- \* Linecards connected to WDM transmission system and local ports via ROB
- \* Optical express paths added to linecard
- \* ISP traffic engineering applied to realize 100 Tbps capacity
- \* Supports multiple architectures
  - \* Multistage
  - \* Distributed
  - \* Balanced
- \* Support any ratio of express WDM traffic, optically packet routed traffic, and added/dropped traffic
- \* Modular capacity growth of WDM on a link-by-link basis

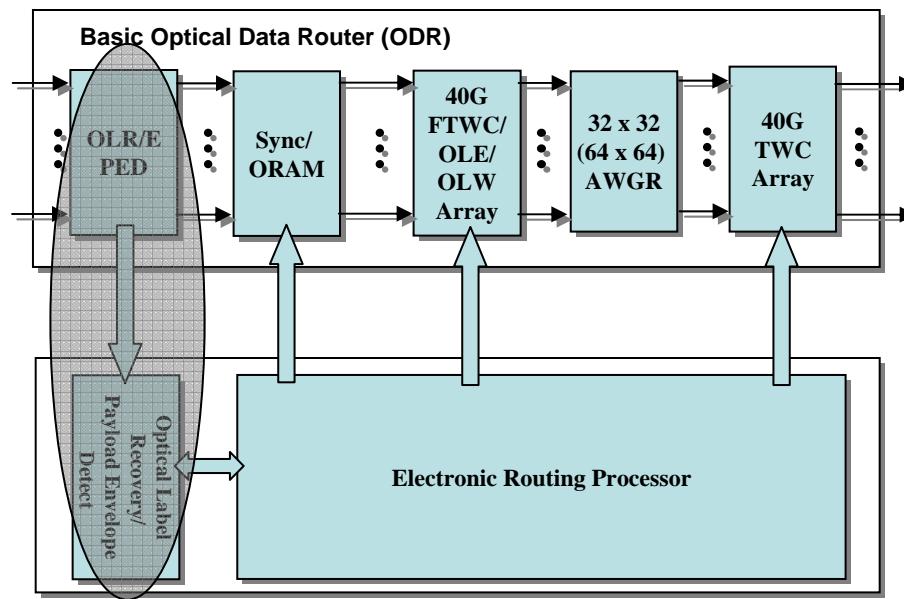


# Optically Buffered ODR



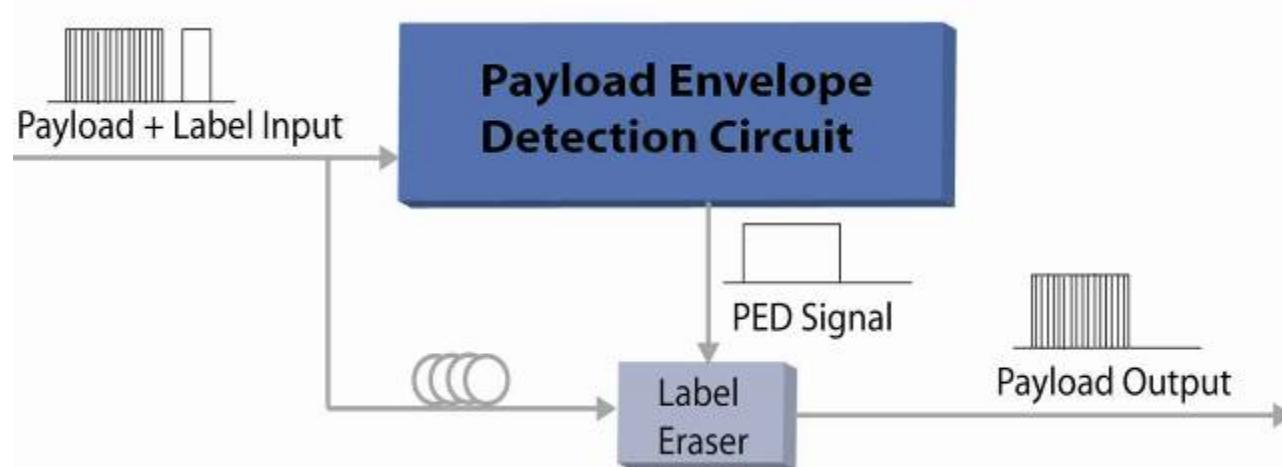


# Optical Header Recovery and Payload Envelope Detect



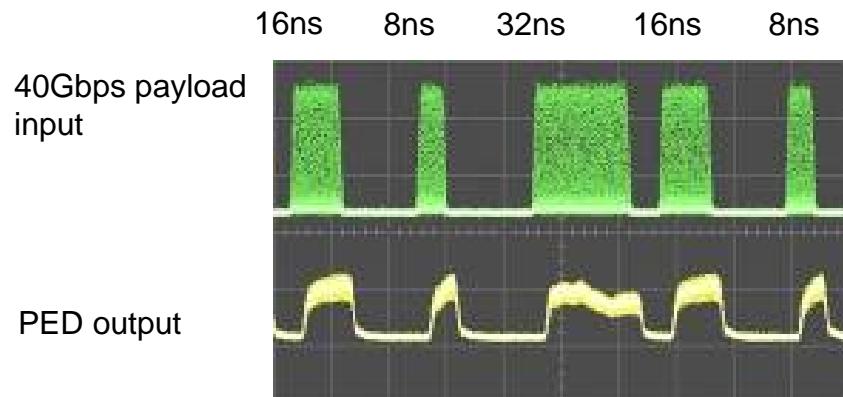
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# Payload Envelope Detection (PED)

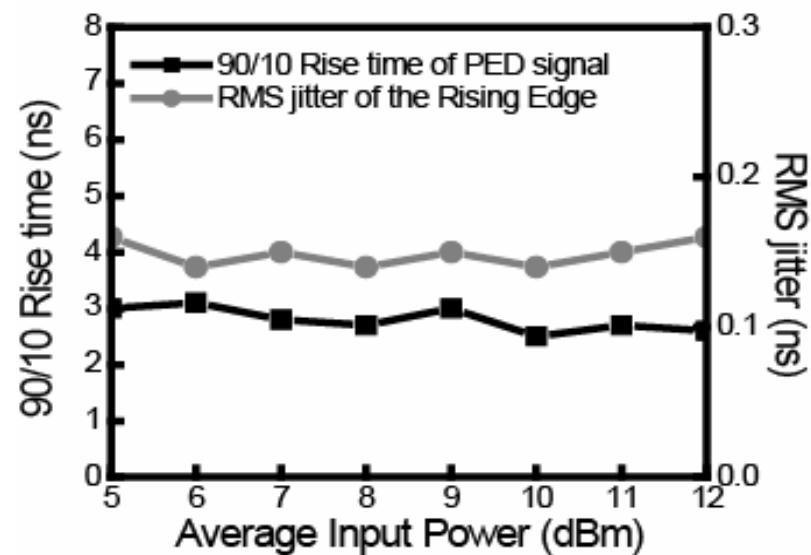
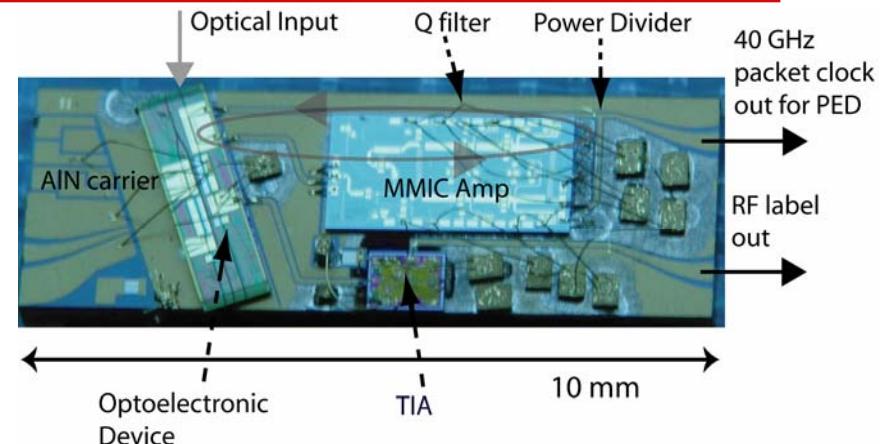


# Phase 1 Hybrid PED

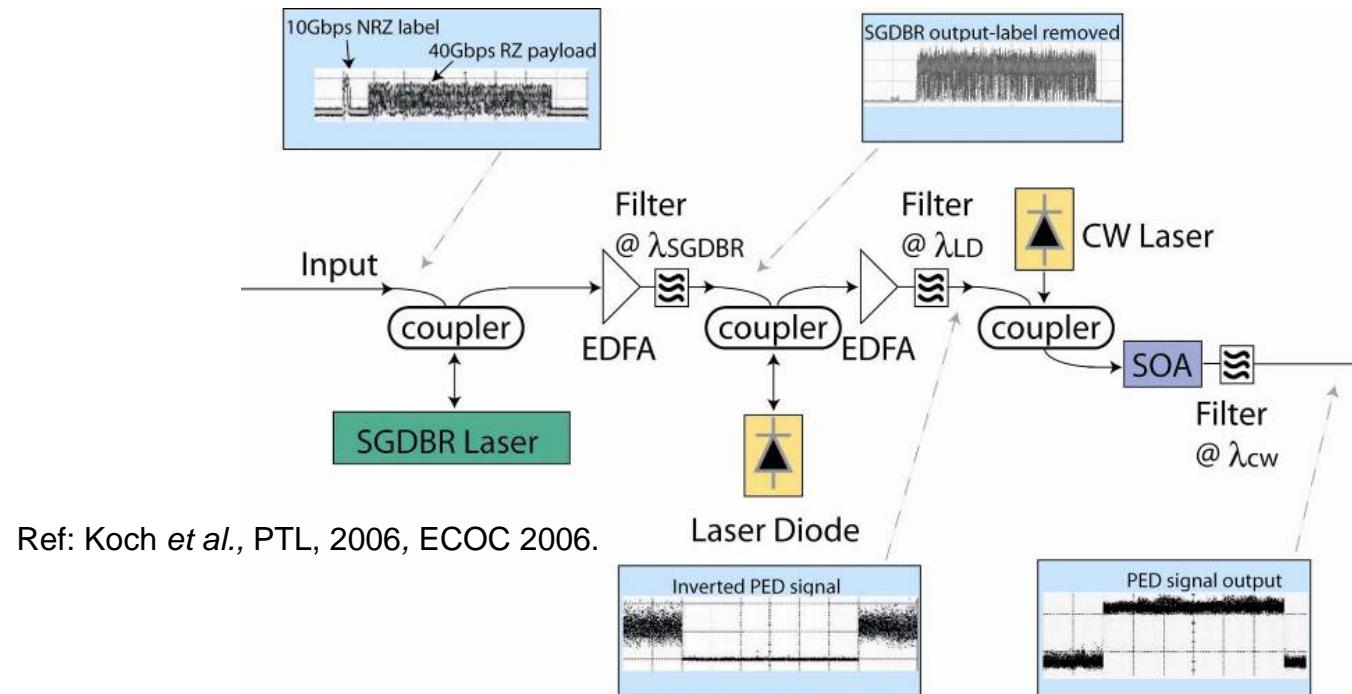
- \* **Hybrid Integrated Optoelectronic Payload Envelope Detection (PED) device**
  - \* variable length PED signals generated
  - \* 3ns rise/fall time
  - \* 150 ps RMS jitter
  - \* ~7 dB input power dynamic range
  - \* Removed and inserted labels using this PED signal with <1dB power penalty



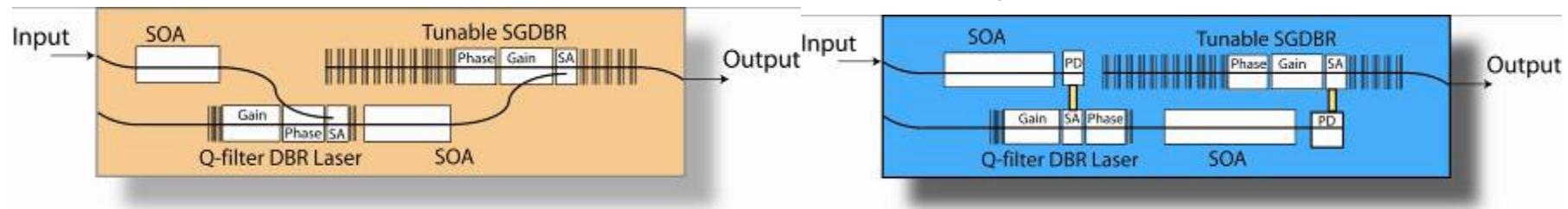
Ref: Koch et al., OFC 2006, JLT, 2006, Optics Express, 2006.



# Phase II - All-Optical PED



**Integrated all-optical PED:** Compact, single component, low power consumption, Less expensive, low latency



# All-Optical 3R Regeneration

## \*Goals

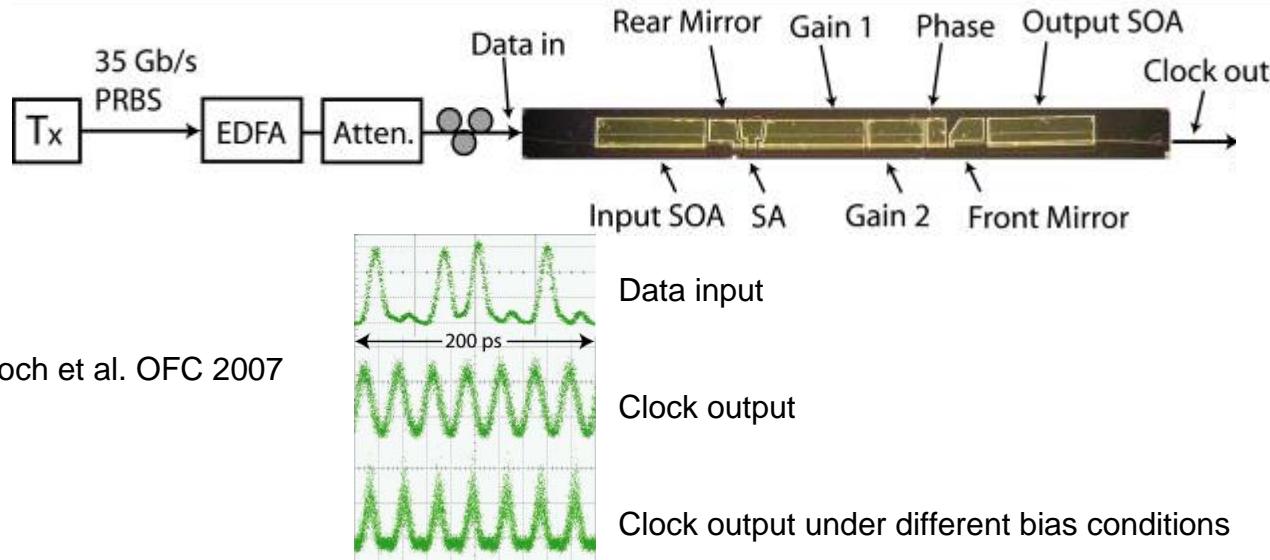
- \*Precisely determine the repetition rate
- \*Very high quality pulse reshaping and re-timing
- \*integrated all-optical 3R regenerator

## \*Approach

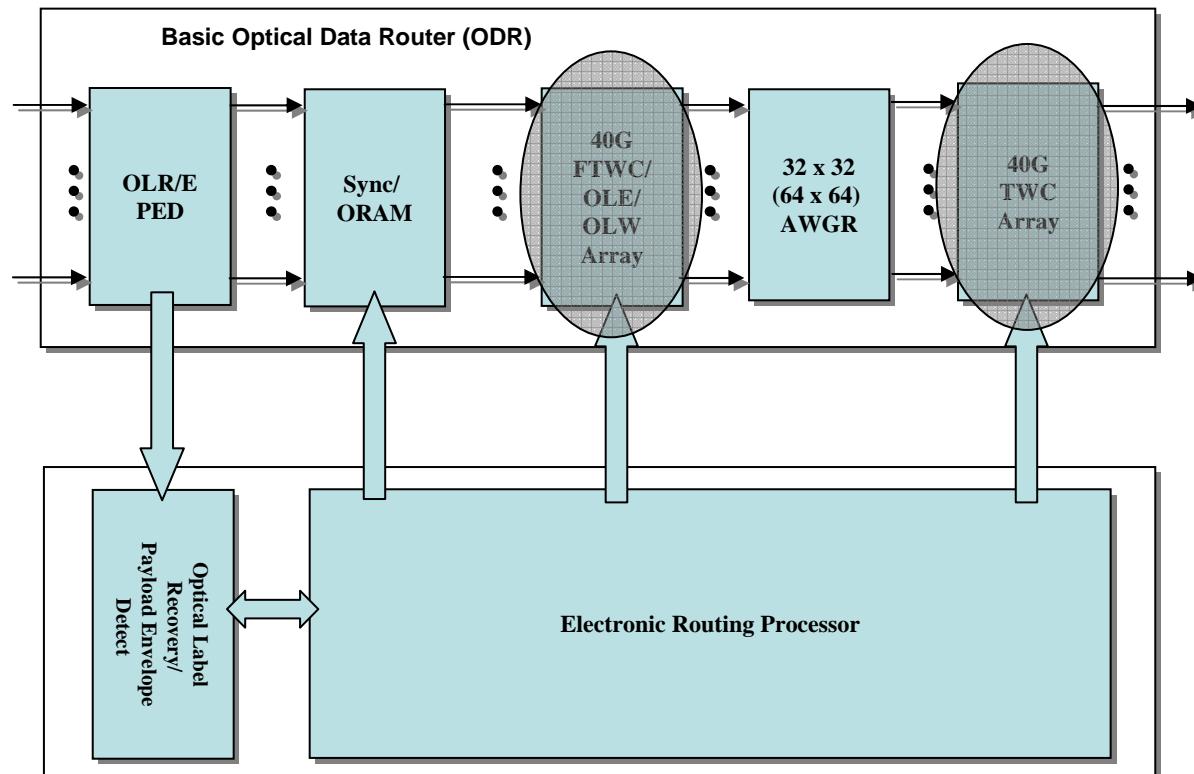
- \*Integrated Mode Locked Lasers with optical gates
- \*Short, transform limited pulses
- \*Very high extinction ratios
- \*High output powers possible
- \*Integrate MLLs with other components



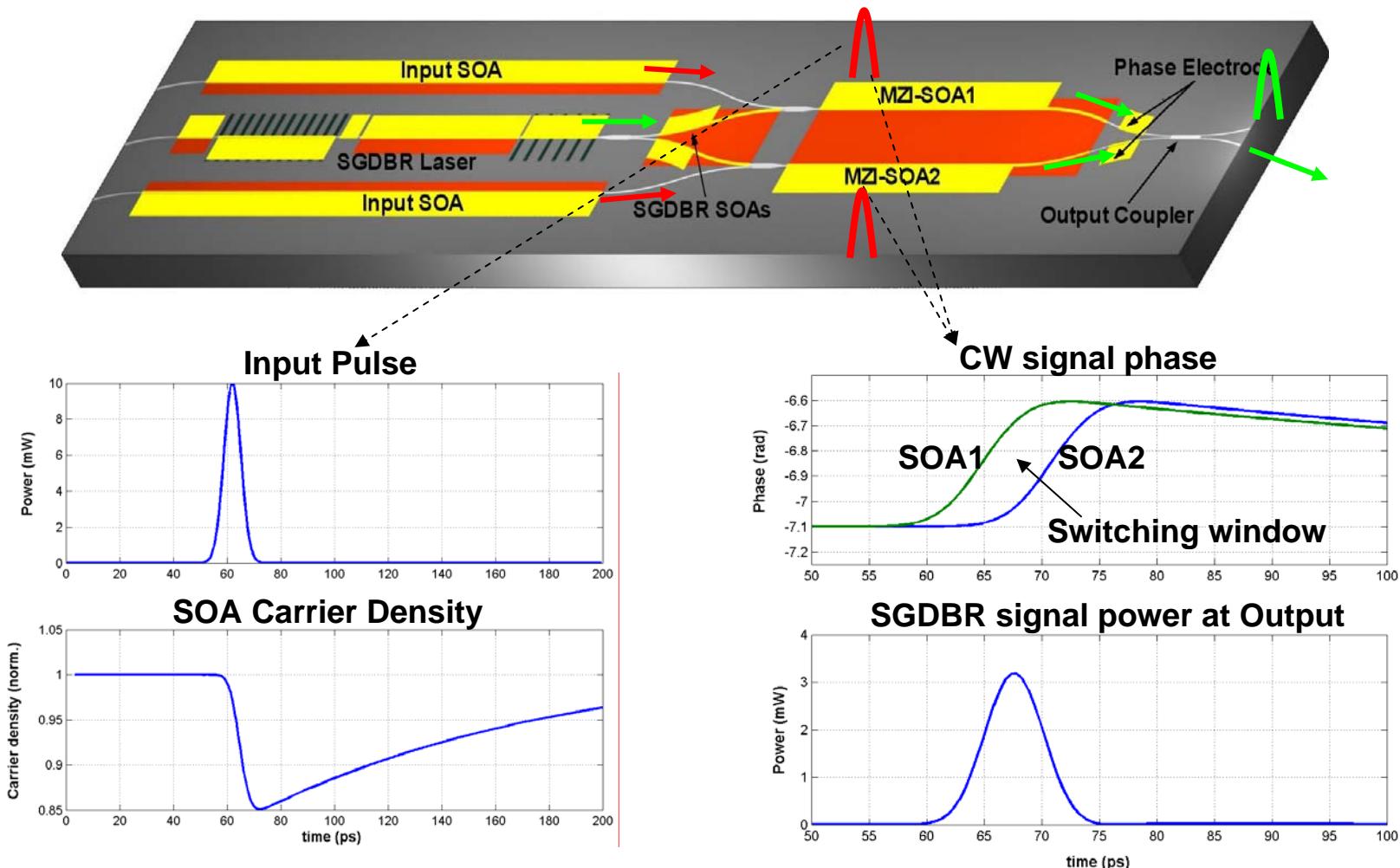
### Clock Recovery with tunable output pulselength



# 40Gbps Wavelength Converter Technology



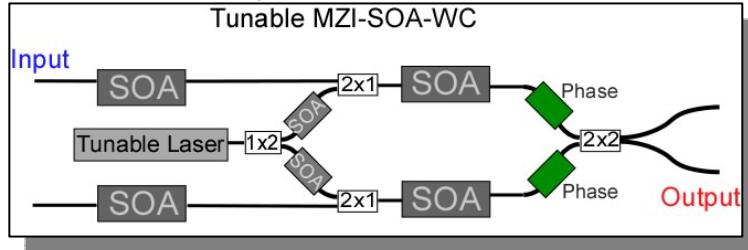
# 40Gb/s Packet WC: Operating Principle



# 40Gbps Monolithic Widely-Tunable Differential Wavelength Converters

## Gen. 1 : External Delay

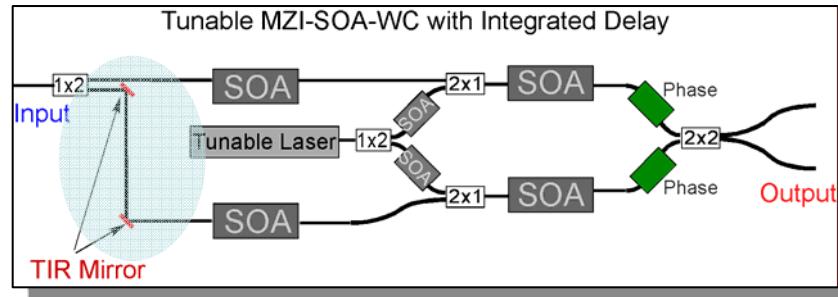
Chip Area =  
2.5mm<sup>2</sup>



V. Lal, M. L. Mašanović, J. A. Summers, L. A. Coldren, and D. J. Blumenthal, "40Gbps Operation of an Offset Quantum Well Active Region Based Widely Tunable All-Optical Wavelength Converter," Optical Fiber Communication Conference, Anaheim, California, 2005.

## Gen. 2 : Integrated Input Differential Delay

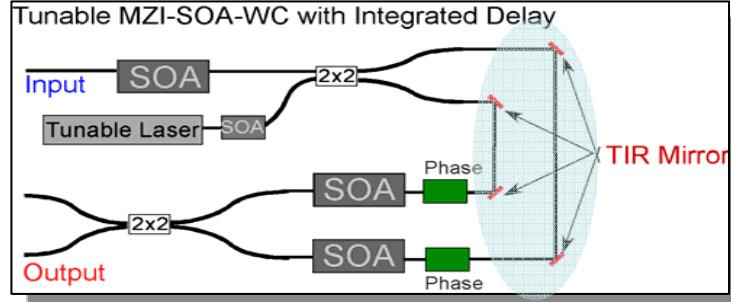
Chip Area =  
3.8mm<sup>2</sup>



J. A. Summers, V. Lal, M. L. Mašanović, L. A. Coldren, and D. J. Blumenthal, "Widely-Tunable All-Optical Wavelength Converter Monolithically Integrated with a Total Internal Reflection Corner Mirror Delay Line for 40Gbps RZ Operation," Integrated Photonics Research and Applications (IPRA '05), Paper IMC5, San Diego, California, April 11-13, 2005.

## Gen. 3 : Compact Integrated Balanced Delay

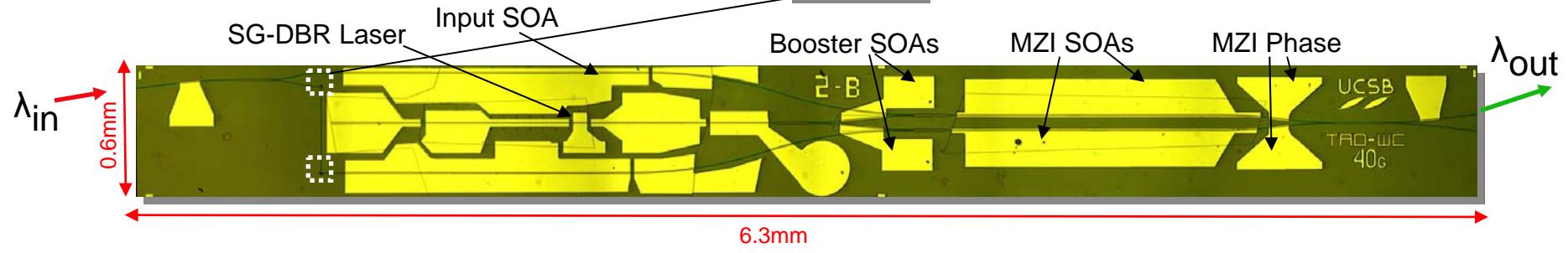
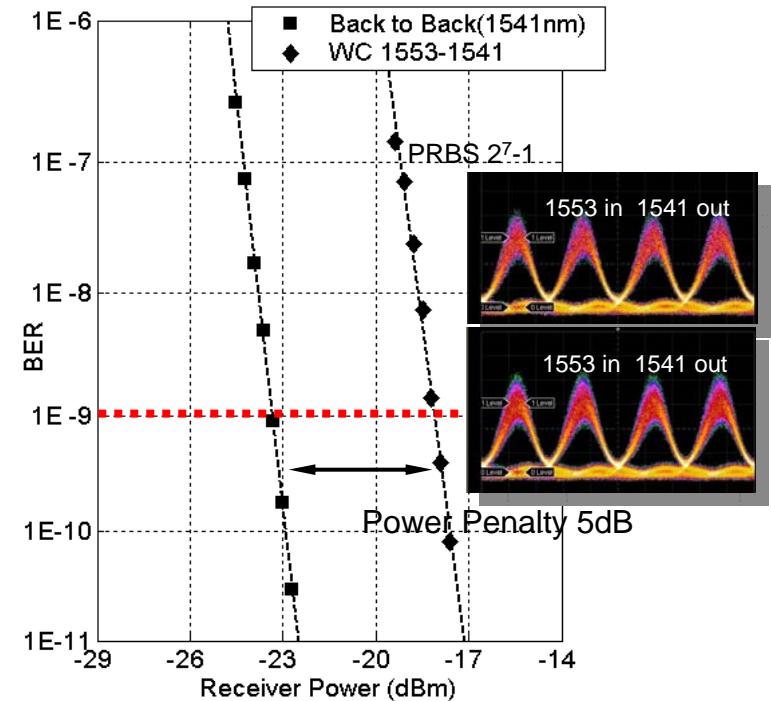
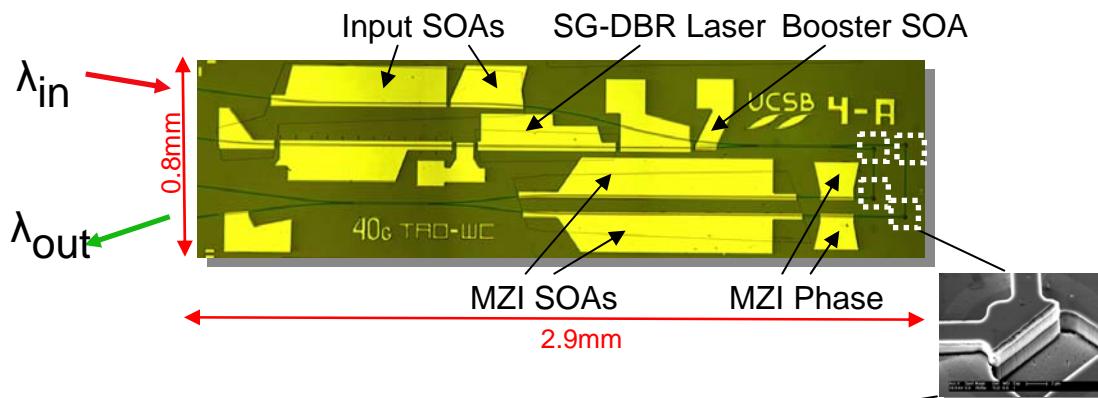
Chip Area =  
2.4mm<sup>2</sup>



V. Lal, J. A. Summers, M. L. Masanovic, L. A. Coldren, and D. J. Blumenthal, "Novel Compact InP-based Monolithic Widely Tunable Differential Mach-Zehnder Interferometer Wavelength Converter for 40Gbps Operation," Indium Phosphide and Related Materials, Opto-I (IPRM '05), Glasgow, Scotland, May 8-12.

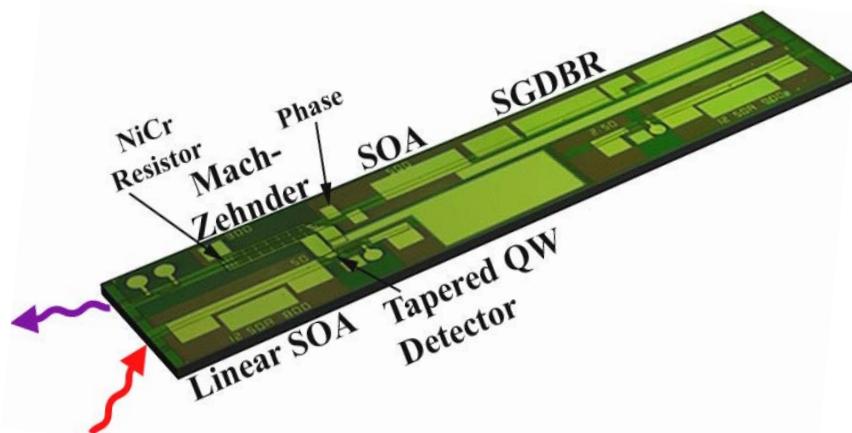
## 40G Tunable Wavelength Converters with Integrated Delay

- \* World's First Monolithic Integrated 40G Tunable All-Optical WC
- \* On-chip delay lines using TIR mirrors for RZ operation
- \* Optical preamplifiers
- \* Optical power splitters and combiners
- \* Mach-Zehnder interferometer optical wavelength converter
- \* Tunable laser
- \* Laser booster optical amplifier

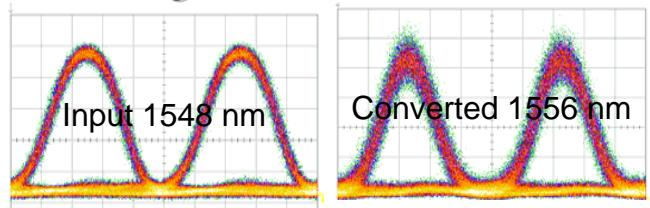


# Field-based Monolithic Wavelength Converters

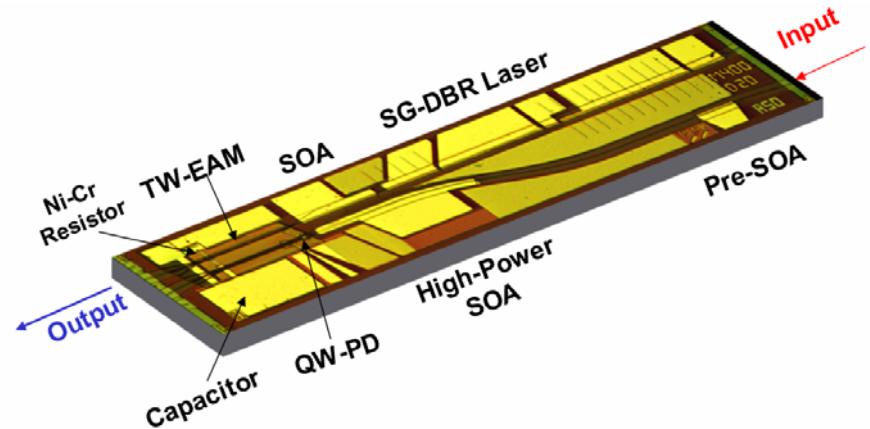
Mach-Zehnder



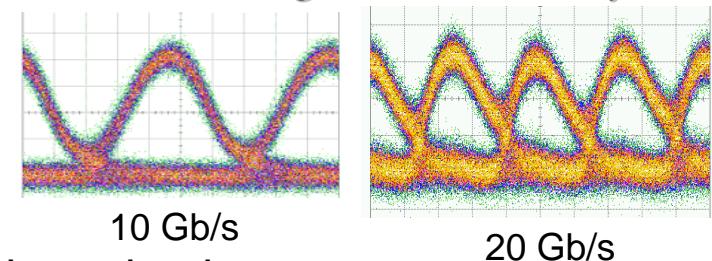
Wavelength Conversion at 10 Gb/s



Electro-Absorption



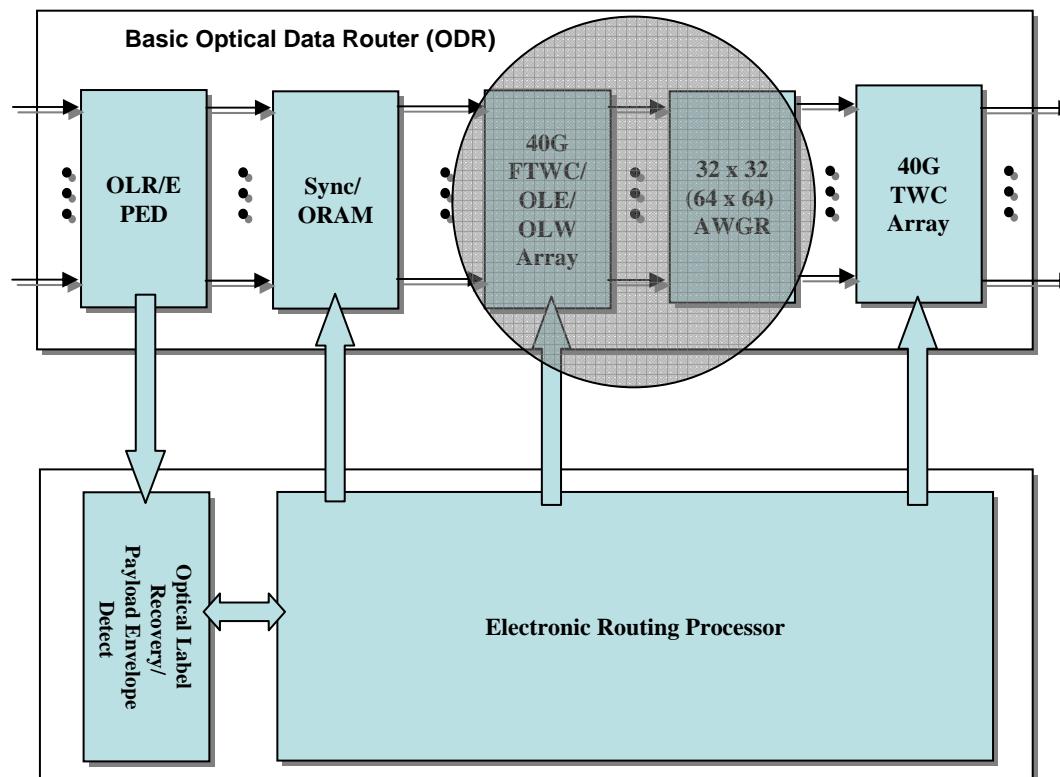
Wavelength Converted Eyes



- ✿ Integrated RF interconnections and terminations
- ✿ Bandwidth greater than 20 GHz
  - ✿ Frequency response limited by QW detectors

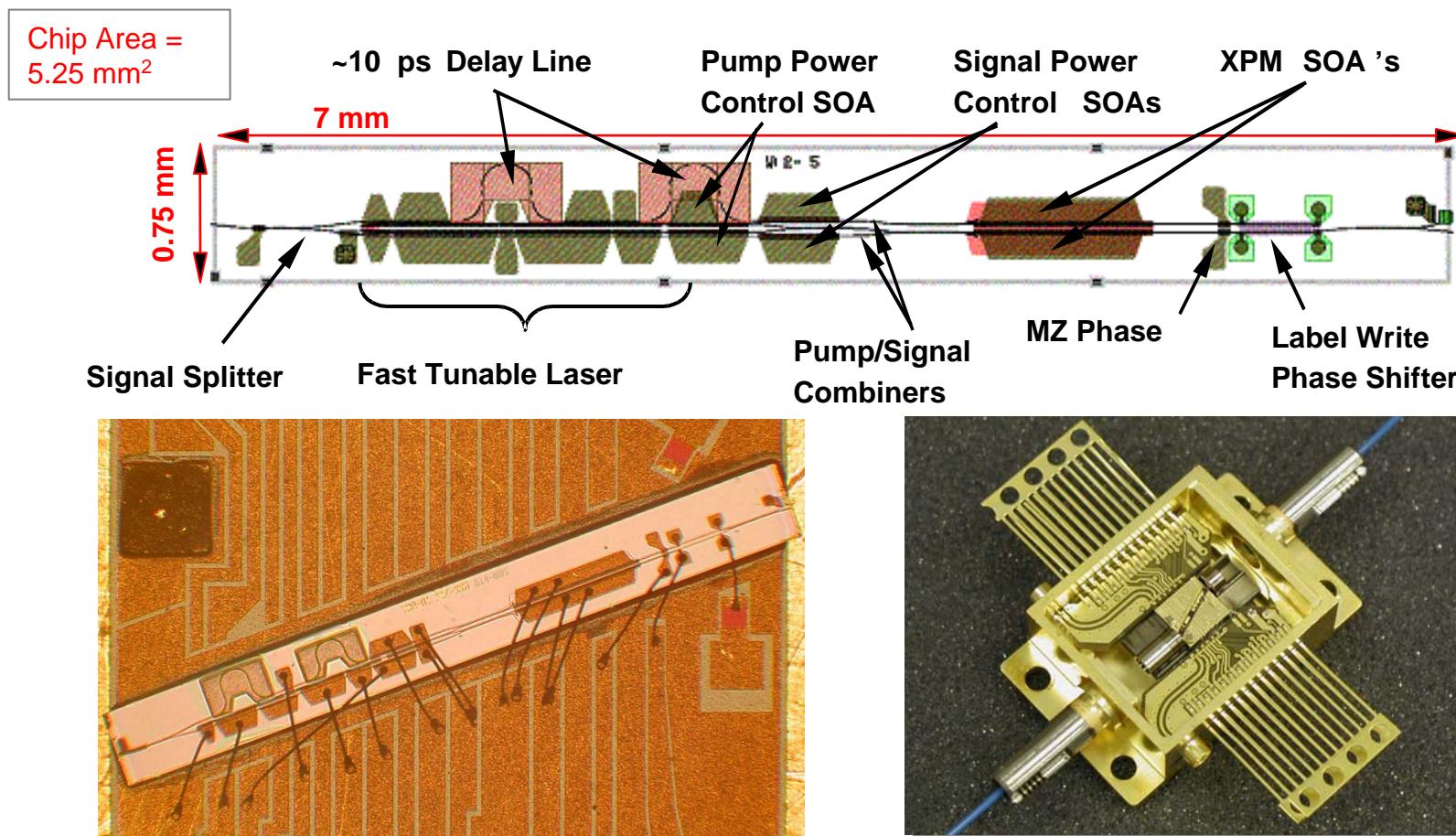
**A. Tauke-Pedretti, J. Barton, L. Johansson, M. Dummer, M. Sysak, J. Raring, L. Coldren**

# Packet Forwarding





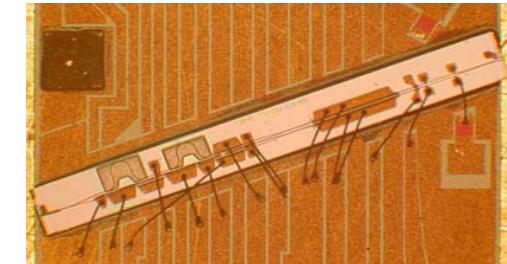
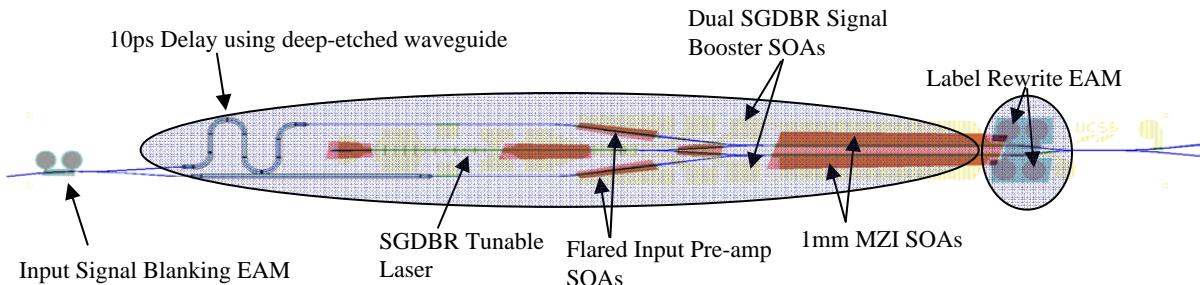
# PFC Chip and Module



"Monolithic Widely Tunable Optical Packet Forwarding Chip in InP for All-Optical Label Switching with 40 Gbps Payloads and 10 Gbps Labels," V. Lal, M. Mašanović, D. Wolfson, G. Fish, C. Coldren, and D. J. Blumenthal, Accepted for presentation as Postdeadline Paper, ECOC 2005 Glasgow, Scotland.

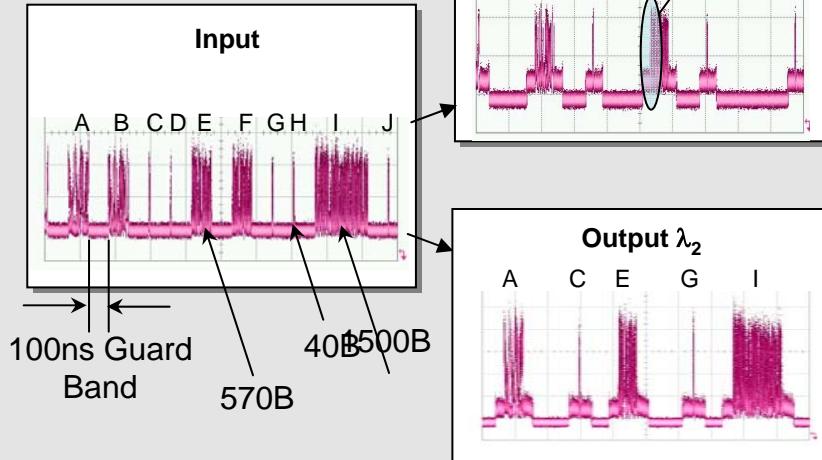


# PFC Packet $\lambda$ -Conversion and OH Re-Write

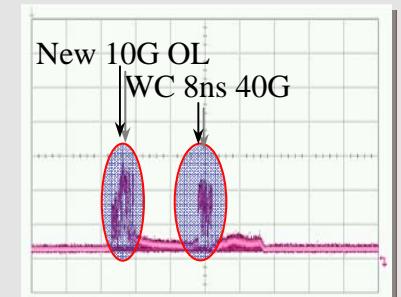
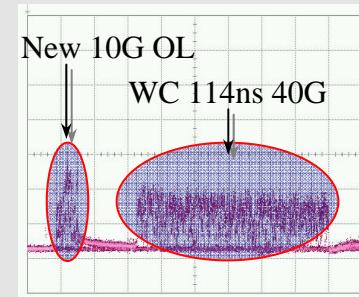
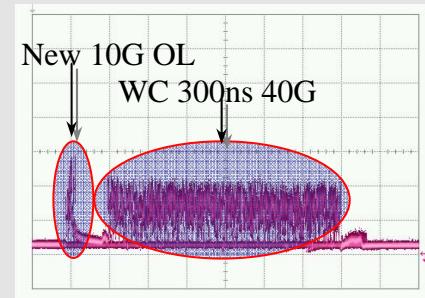


## Variable Length Packets and Dynamic Forwarding + 100ns Guard Band

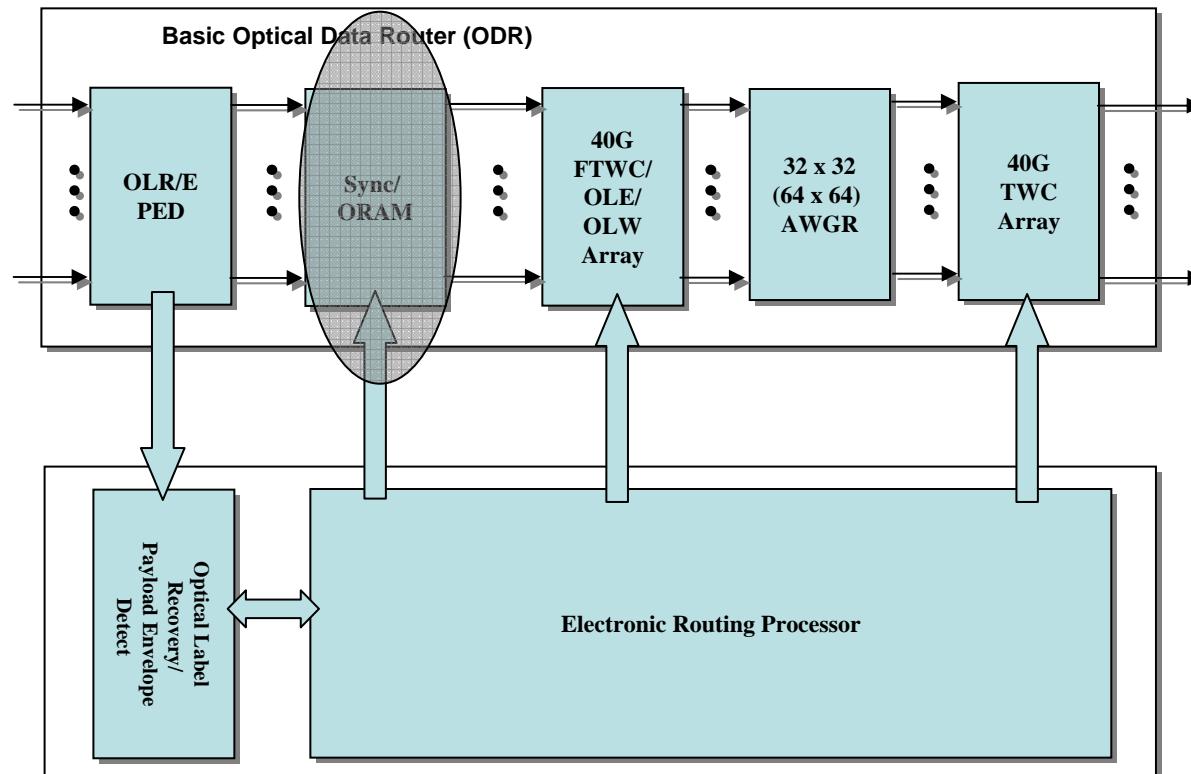
iMix 7:4:1  $\rightarrow$  40B:570B:1500B



## 10G Optical Header Re-Write

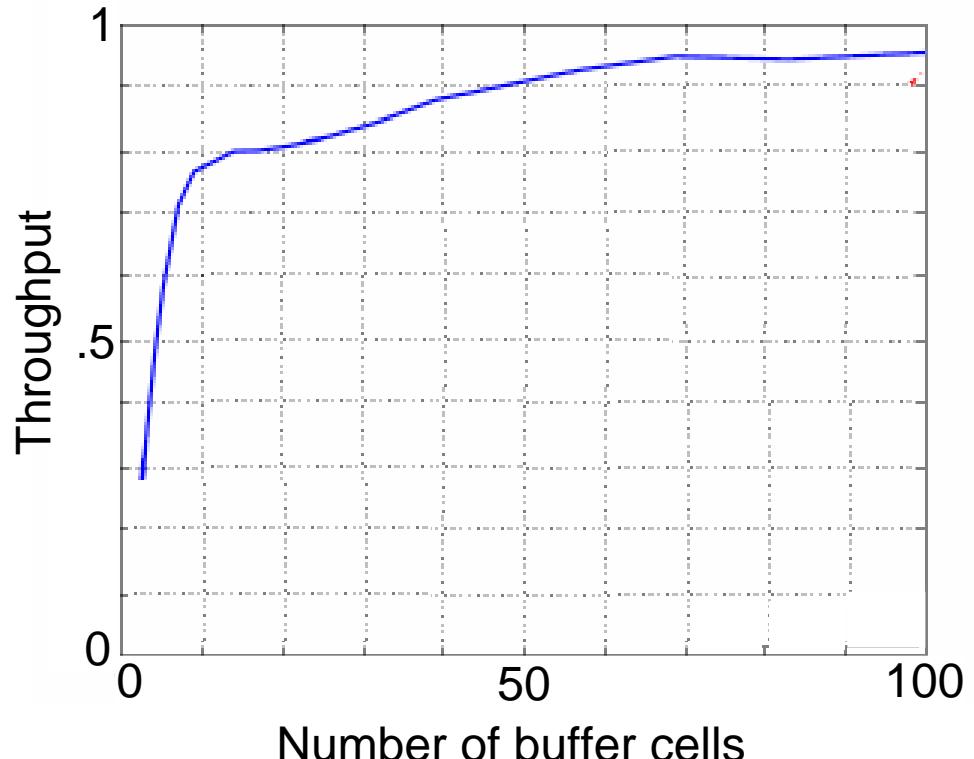


# Synchronizers and Buffers



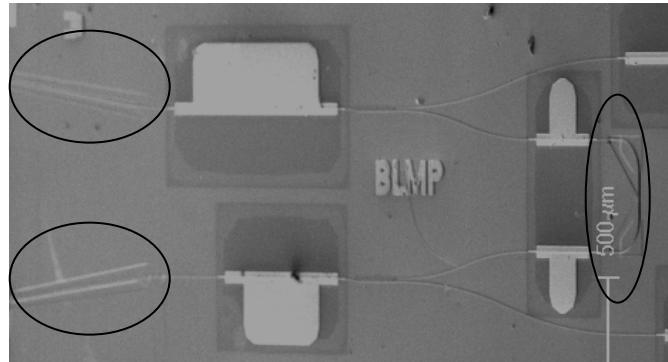
# Small Buffer Performance

- \* Optical routers will receive access flows at much lower bandwidths than backbone links  
-> naturally spaces packets
- \* Small numbers of buffers make a large difference.
- \* Only 20-50 buffers are needed (assuming customer is willing to sacrifice 25% of link capacity)
- \* Studies were performed by Professor McKeown's group (Enachescu et al ACM/SIGCOMM 2005)

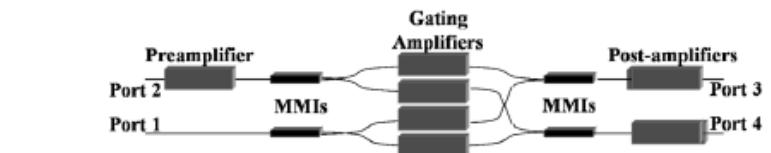


*Output-queued router. An increase of 60% in throughput is achieved with <15 buffers.*

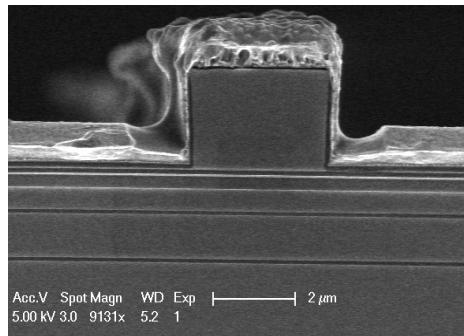
# Hybrid Recirculating Packet Buffers



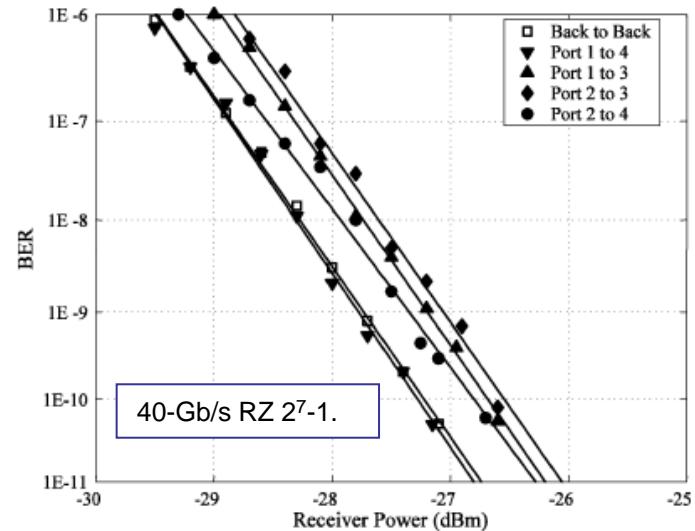
Input and output of a buffer showing spot size converters (left) and 90° bends (right).



Fabricated SOA gate matrix switch wirebonded to an aluminum nitride submount.

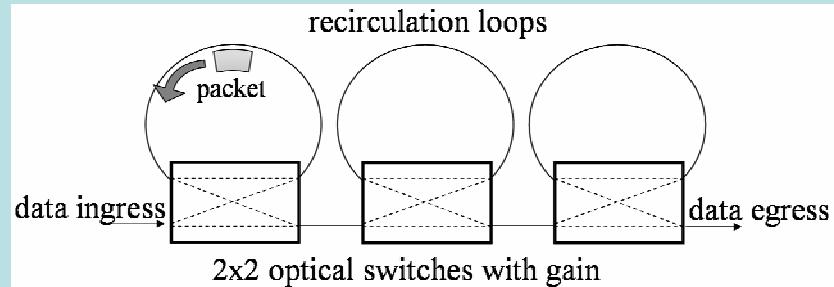


Epitaxial layers, including lower two 1.2 Q layers for spot size conversion.



# Optical Buffer (ORAM)

- ★ Recirculating buffers for on-chip, integrated optical packet buffer with dynamic control of storage time and random read.



- ★ Hybrid buffers are designed to combine the fast switching available with InGaAsP-based photonic chips and the low propagation loss available with silica waveguides.

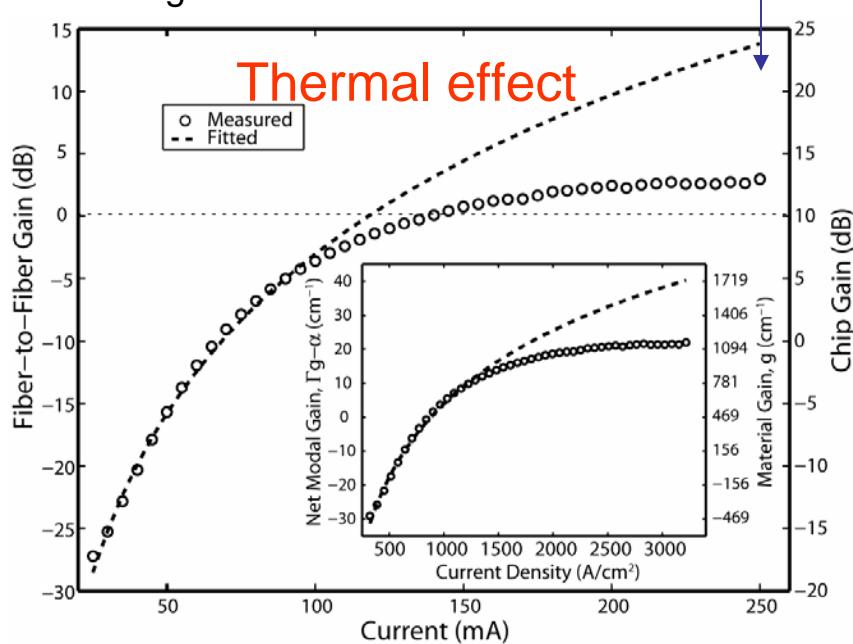
- ★ Silica waveguides have been designed and fabricated. Testing shows loss of less than 0.02 dB/cm.

- ★ Recent device fabrication shows good results on improved design features such as spot size converters and 90° bends, however out-sourced material regrowth created contamination which limited performance.

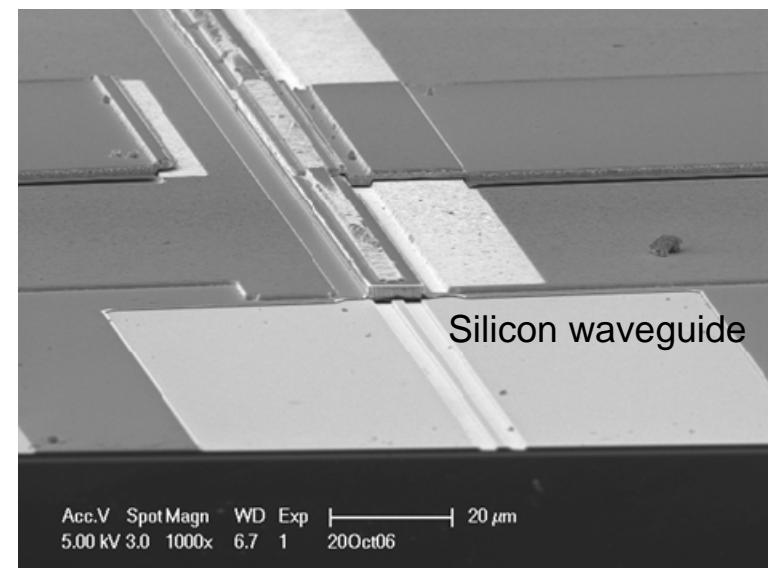
- ★ InGaAsP gate matrix switches were designed, fabricated, and tested. Error-free performance was shown with negligible power penalty. [Burmeister, *Photon. Technol. Lett.*, vol. 18, no. 1, 2006].

# Integrated optical buffer-silicon evanescent amplifier

- \* **Long Term Goal:** Demonstrate fully integrated optical packet buffer.
- \* **Short Term Goals:** 1) Demonstrate 10 passes around loop. 2) Demonstrate gain based switch architecture.
- \* **1<sup>st</sup> generation results**
  - \* Maximum fiber to fiber gain: 3 dB
  - \* Estimated chip gain of 13 dB
  - \* Thermally limited by heat generation due to high series resistance



- \* **2<sup>nd</sup> generation Objectives**
  - \* Maximum gain > 20 dB
  - \* Silicon Input/Output waveguide for integration with silicon delay lines
- \* **Current status**
  - \* Fabrication is finished.
  - \* Gain ripple because of reflections at the junction of silicon and III-V section
  - \* Better transition design needed such as tapers on III-V side.



# Chip Level 2x2 Optically Buffered ODR

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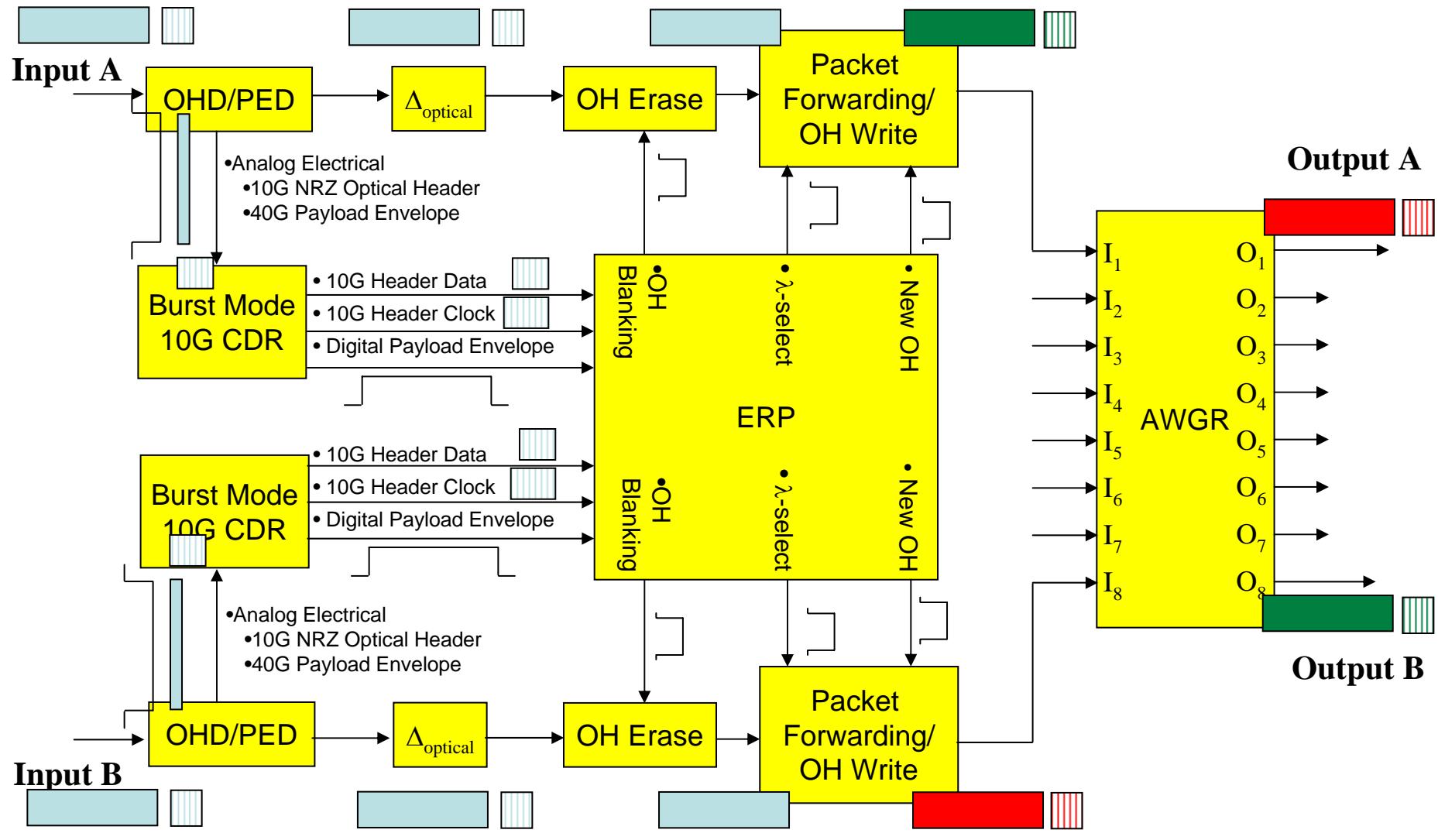


[Movie File](#)



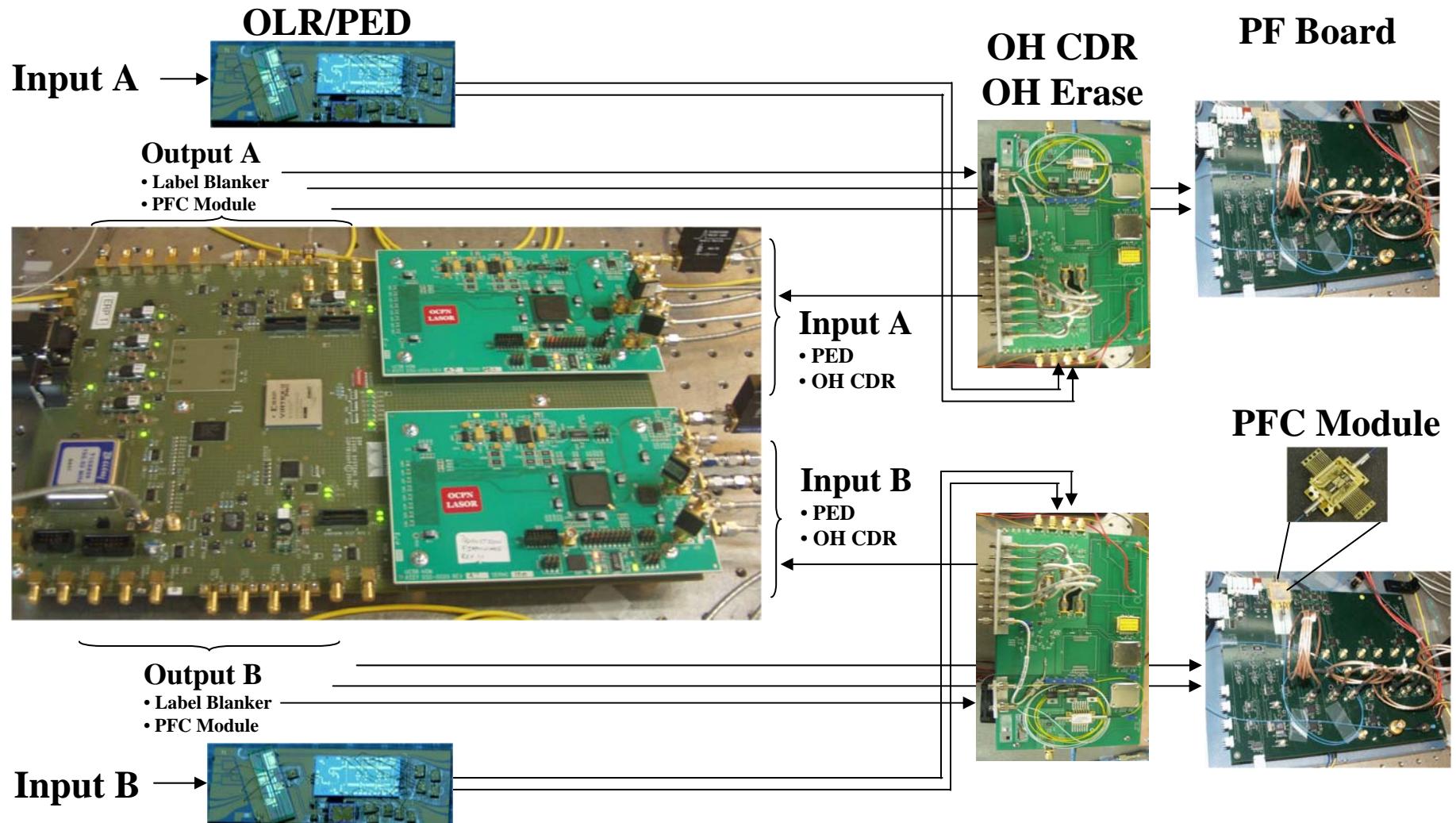
# System Demonstrations

# 2x2 ODR Functional Diagram

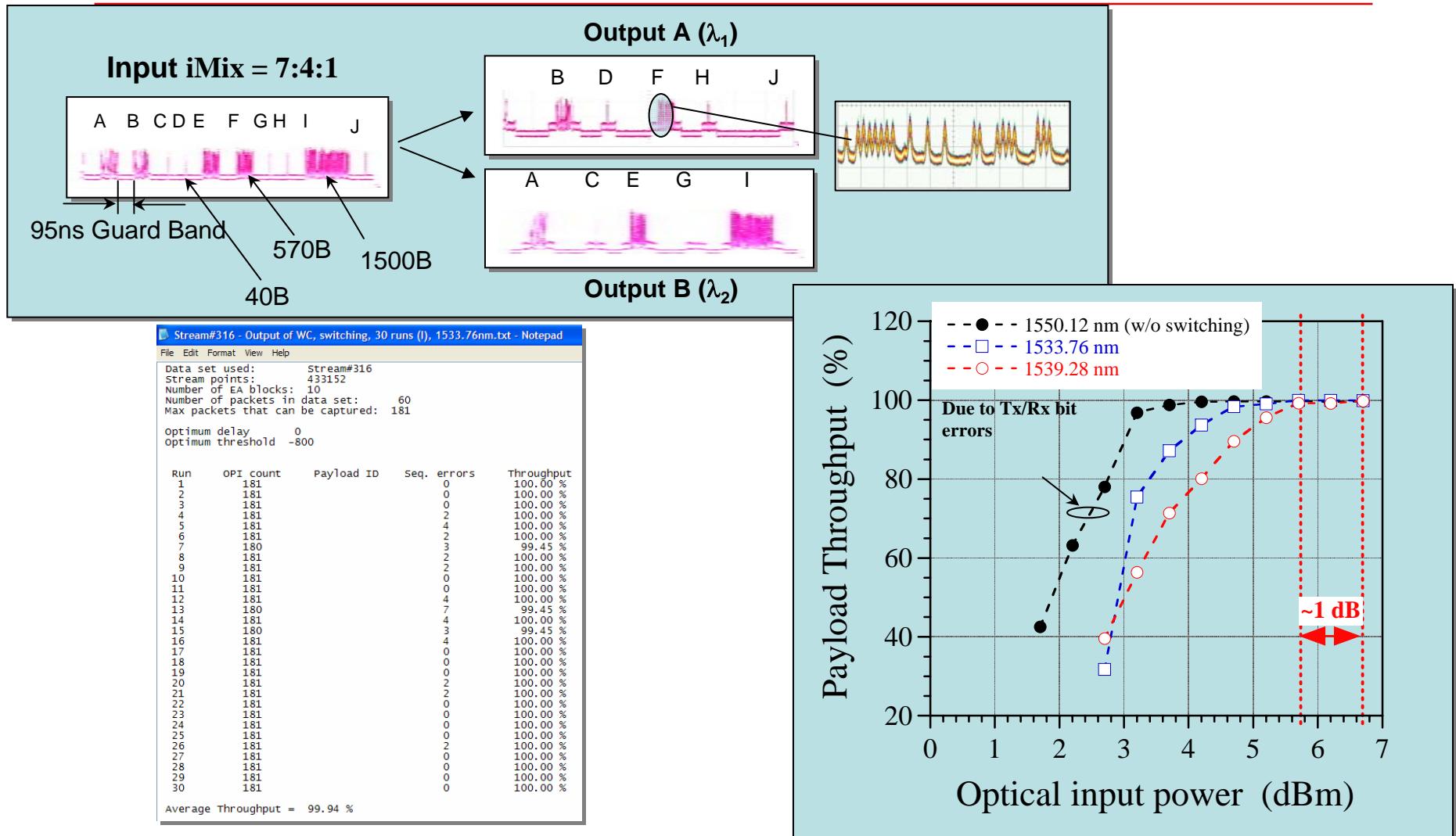




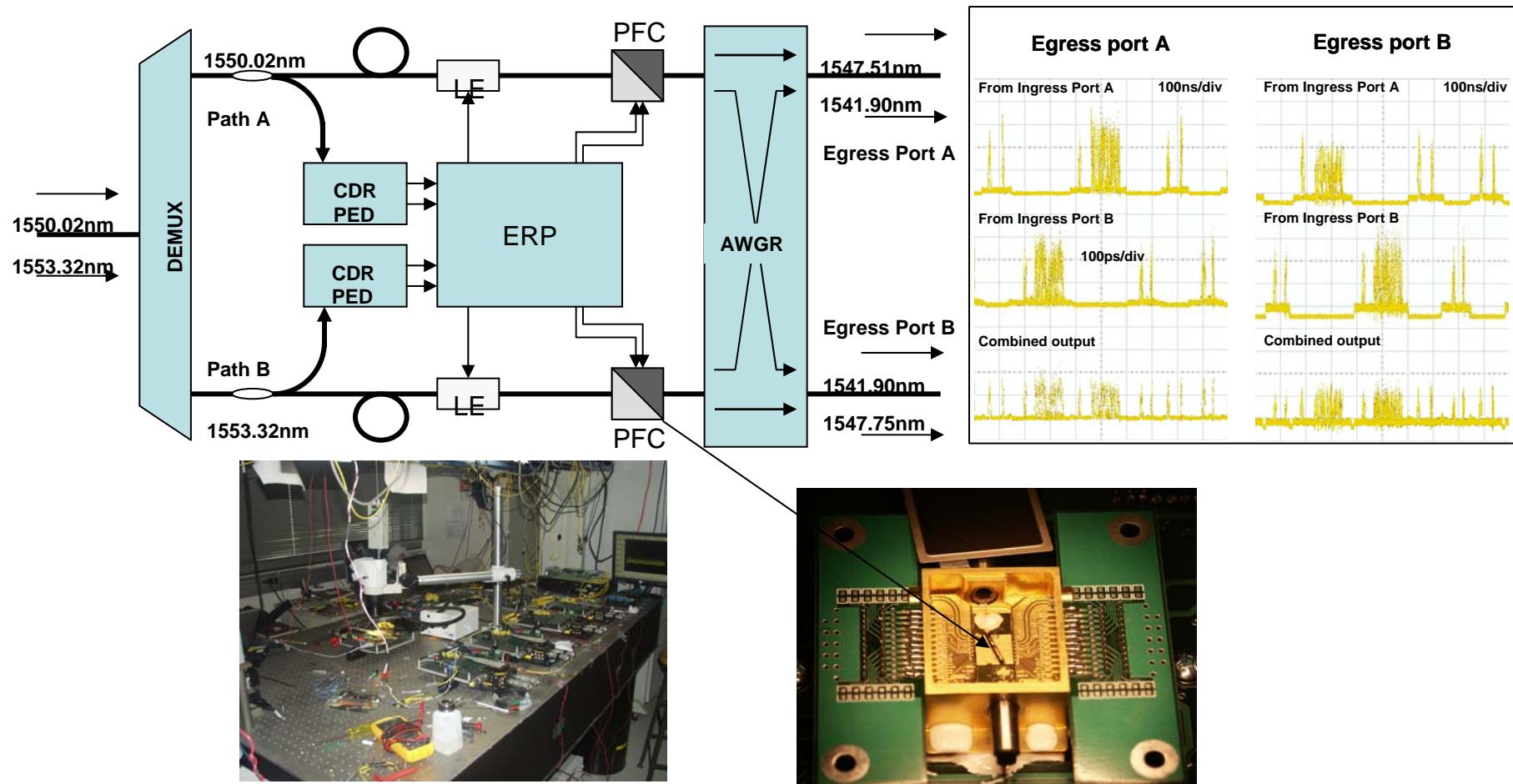
# Electronic Control



# Layer-2/3 Results: Payload Throughput



## 2x2 ODR Demonstration



H. Poulsen, W. Donat, V. Lal, M. Mashanovitch, G. Epps, D. Civello, C. Coldren, G. Fish, D. Blumenthal, "Demonstration of Simultaneous Multiplexing/Demultiplexing Operation of an All-Optical 2x2 Packet Switch with Asynchronous Variable-length Optically Labeled 40Gbps Packets," Accepted for presentation at ECOC 2006.



# CSWDM and LASOR Building Blocks

- ✿ Monolithic dynamic wavelength converters
  - ✿ Regenerative, cascadable, input-output isolation
  - ✿ Two stage - internal wavelengths or wavebands
  - ✿ Internal wavelength optimized signal processing and memories
- ✿ Dynamic data (packet) storage cells
- ✿ Dynamic data (packet) synchronization cells
- ✿ Data envelope detectors
- ✿ All-optical clock and data recovery elements
- ✿ Switches and gain blocks
- ✿ Optical carrier filters
- ✿ Optical data filters



# Future Directions

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- ＊ Advance 2-stage wavelength converters with intermediate signal processing stages
- ＊ Ultra low-loss waveguides
- ＊ Phonon engineering for heat removal
- ＊ Integrated coherent wavelength converters
- ＊ Integration of FPGA electronics + digital/analog + photonics
- ＊ All-optical FPGAs made with programmable optical cells
- ＊ New composite material systems that are engineered for optimum optical performance + thermal properties + integration with Si electronics